



# KU968 COM Express Compact Module User's Manual

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## **COM Express Specification Reference**

PICMG<sup>®</sup> COM Express Module<sup>™</sup> Base Specification.

http://www.picmg.org/

## FCC and DOC Statement on Class B

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and the receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio TV technician for help.

#### **Notice:**

- The changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.
- 2. Shielded interface cables must be used in order to comply with the emission limits.

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## **Warranty**

- Warranty does not cover damages or failures that arised from misuse of the product, inability to use the product, unauthorized replacement or alteration of components and product specifications.
- 2. The warranty is void if the product has been subjected to physical abuse, improper installation, modification, accidents or unauthorized repair of the product.
- Unless otherwise instructed in this user's manual, the user may not, under any circumstances, attempt to perform service, adjustments or repairs on the product, whether in or out of warranty. It must be returned to the purchase point, factory or authorized service agency for all such work.
- 4. We will not be liable for any indirect, special, incidental or consequencial damages to the product that has been modified or altered.

## **Static Electricity Precautions**

It is quite easy to inadvertently damage your PC, system board, components or devices even before installing them in your system unit. Static electrical discharge can damage computer components without causing any signs of physical damage. You must take extra care in handling them to ensure against electrostatic build-up.

- To prevent electrostatic build-up, leave the system board in its anti-static bag until you are ready to install it.
- 2. Wear an antistatic wrist strap.
- Do all preparation work on a static-free surface.
- 4. Hold the device only by its edges. Be careful not to touch any of the components, contacts or connections.
- Avoid touching the pins or contacts on all modules and connectors. Hold modules or connectors by their ends.



#### **Important:**

Electrostatic discharge (ESD) can damage your processor, disk drive and other components. Perform the upgrade instruction procedures described at an ESD workstation only. If such a station is not available, you can provide some ESD protection by wearing an antistatic wrist strap and attaching it to a metal part of the system chassis. If a wrist strap is unavailable, establish and maintain contact with the system chassis throughout any procedures requiring ESD protection.

## **Safety Measures**

To avoid damage to the system:

Use the correct AC input voltage range.

To reduce the risk of electric shock:

Unplug the power cord before removing the system chassis cover for installation or servicing. After installation or servicing, cover the system chassis before plugging the power cord.

## **About the Package**

The package contains the following items. If any of these items are missing or damaged, please contact your dealer or sales representative for assistance.

- One KU968 board
- One heat sink (Height: 23.8mm)

## **Optional Items**

- COM332-B carrier board kit
- Heat spreader (Height: 11mm)

The board and accessories in the package may not come similar to the information listed above. This may differ in accordance with the sales region or models in which it was sold. For more information about the standard package in your region, please contact your dealer or sales representative.

## **Before Using the System Board**

Before using the system board, prepare basic system components.

If you are installing the system board in a new system, you will need at least the following internal components.

• Storage devices such as hard disk drive, etc.

You will also need external system peripherals you intend to use which will normally include at least a keyboard, a mouse and a video display monitor.

# **Chapter 1 - Introduction**

## **Specifications**

SYSTEM	Processor	7th Generation Intel® Core™ Processors, BGA 1356 Intel® Core™ i7-7600U Processor, Dual Core, 4M Cache, 2.8GHz (3.9GHz), 15W Intel® Core™ i5-7300U Processor, Dual Core, 3M Cache, 2.6GHz (3.5GHz), 15W Intel® Core™ i3-7100U Processor, Dual Core, 3M Cache, 2.4GHz, 15W Intel® Celeron® Processor 3965, Dual Core, 2M Cache, 2.2GHz, 15W
	Memory	16GB DDR4 Memory Down Dual Channel DDR4 2133MHz
	BIOS	Insyde SPI 128Mbit
GRAPHICS	Controller	Intel® HD Graphics
	Feature	OpenGL 5.0, DirectX 12, OpenCL 2.1 HW Decode: AVC/H.264, MPEG2, VC1/WMV9, JPEG/MJPEG, HEVC/H265, VP8, VP9 HW Encode: AVC/H.264, MPEG2, JPEG, HEVC/H265, VP8, VP9
	Display	1 x VGA/DDI (DDI available upon request) 1 x LVDS/eDP (eDP available upon request) 1 x DDI VGA: resolution up to 1920x1200 @ 60Hz LVDS: dual channel 24-bit, resolution up to 1920x1200 @ 60Hz eDP: resolution up to 4096x2304 @ 60Hz HDMI: resolution up to 4096x2160 @ 30Hz DP++: resolution up to 4096x2304 @ 60Hz
	Triple Displays	VGA + LVDS + DDI DDI + eDP + DDI
EXPANSION	Interface	5 PCIe x1 or 4 PCIe x1 + 1 PCIe x4 or 3 PCIe x1 + 2 PCIe x2 (support up to 5 devices and 8 lanes) 1 x LPC 1 x I <sup>2</sup> C 1 x SMBus 2 x UART (TX/RX)
AUDIO	Interface	HD Audio
ETHERNET	Controller	1 x Intel® I219LM with iAMT11.0 PCIe (10/100/1000Mbps)
I/O	USB	4 x USB 3.0 8 x USB 2.0
	SATA	3 x SATA 3.0 (up to 6Gb/s) RAID 0/1/5
	DIO	1 x 8-bit DIO

WATCHDOG TIMER	Output & Interval	System Reset, Programmable via Software from 1 to 255 Seconds			
SECURITY	TPM	Available Upon Request			
POWER	Туре	12V, 5VSB, VCC_RTC (ATX mode) 12V, VCC_RTC (AT mode)			
	Consumption	Typical: 3965U: 12V @ 0.2134A (2.5608W) Max.: 3965U: 12V @ 1.3592A (16.3104W)			
OS SUPPORT		Windows: Windows 10 IoT Enterprise 64-bit LINUX: Yocto Project v2.2			
ENVIRONMENT	Temperature	Operating : 0 to 60°C : -45 to 85°C (with heat spreader) Storage: -40 to 85°C			
	Humidity	Operating: 5 to 90% RH Storage: 5 to 90% RH			
	MTBF	866,065 hrs @ 25°C; 422,194 hrs @ 45°C; 238,613 hrs @ 60°C Calculation Model: Telcordia Issue 2 Environment: GB, GC – Ground Benign, Controlled			
MECHANICAL	Dimensions	COM Express® Compact 95mm (3.74") x 95mm (3.74")			
	Compliance	PICMG COM Express® R2.1, Type 6			

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#### **Features**

## Watchdog Timer

The Watchdog Timer function allows your application to regularly "clear" the system at the set time interval. If the system hangs or fails to function, it will reset at the set time interval so that your system will continue to operate.

#### • DDR4

DDR4 delivers increased system bandwidth and improves performance. DDR4 improves the performance at a lower power than DDR3/DDR2.

### Graphics

The integrated Intel® HD graphics engine delivers an excellent blend of graphics performance and features to meet business needs. It delivers enhanced media conversion rates and higher frame rates on 4K Ultra HD videos. These enhancements deliver the performance and compatibility to meet the demand for business and home entertainment applications. Supports 1 x VGA/DDI (DDI available upon request), 1 x LVDS/eDP ( eDP available upon request) and 1 x DDI display interfaces.

#### Serial ATA

Serial ATA is a storage interface that is compliant with SATA 1.0a specification. With speed of up to 6Gb/s (SATA 3.0), it improves hard drive performance faster than the standard parallel ATA whose data transfer rate is 100MB/s. The bandwidth of the SATA 3.0 will be limited by carrier board design.

## Gigabit LAN

The Intel® I219LM Gigabit LAN PHY controller supports up to 1Gbps data transmission.

#### • USB

The system board supports the new USB 3.0. It is capable of running at a maximum transmission speed of up to 5 Gbit/s (625 MB/s) and is faster than USB 2.0 (480 Mbit/s, or 60 MB/s) and USB 1.1 (12Mb/s). USB 3.0 reduces the time required for data transmission, reduces power consumption, and is backward compatible with USB 2.0. It is a marked improvement in device transfer speeds between your computer and a wide range of simultaneously accessible external Plug and Play peripherals.

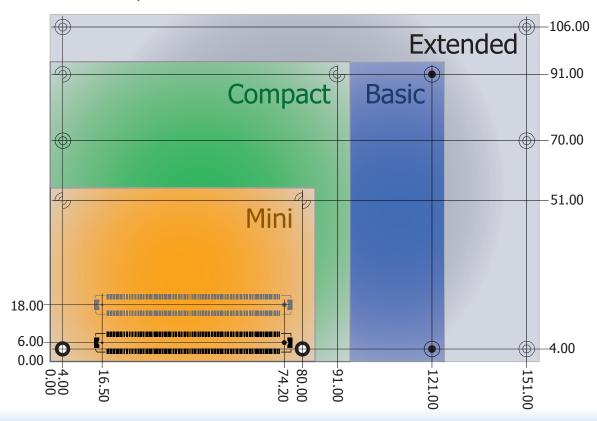
## **Chapter 2 - Concept**

## **COM Express Module Standards**

The figure below shows the dimensions of the different types of COM Express modules.

KU968 is a COM Express Compact module. The dimension is 95mm x 95mm.

- O Common for all Form Factors
- Extended only
- Basic only
- **©** Compact only
- Compact and Basic only
- △ Mini only



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## **Specification Comparison Table**

The table below shows the COM Express standard specifications and the corresponding specifications supported on the KU968 module.

Module Pin-out - Required and Optional Features A-B Connector. PICMG® COM.0 Revision 2.1

		COM Express Module Base	DFI KU968
		Specification Type 6	Type 6
Connector	Feature		
		(No IDE or PCI, add DDI+	
		USB3) Min / Max	
A-B		System I/O	
A-B	PCI Express Lanes 0 - 5	1/6	6
A-B	LVDS Channel A	0 / 1	1
A-B	LVDS Channel B	0 / 1	1
A-B	eDP on LVDS CH A pins	0 / 1	1
A-B	VGA Port	0 / 1	0/1 (Option: DDI2 or VGA)
A-B	TV-Out	NA	NA
A-B	DDI 0	NA	NA
A-B <sup>1</sup>	Serial Ports 1 - 2	0 / 2	2
A-B	CAN interface on SER1	0 / 1	0
A-B	SATA / SAS Ports	1/4	3
A-B	AC'97 / HDA Digital Interface	0 / 1	1
A-B	USB 2.0 Ports	4 / 8	8
A-B	USB Client	0 / 1	0
A-B	USB 3.0 Ports	NA	NA
A-B	LAN Port 0	1 / 1	1
A-B	Express Card Support	1/2	2
A-B	LPC Bus	1 / 1	1
A-B	SPI	1/2	1
A-B		System Managen	nent
A-B <sup>2</sup>	SDIO (muxed on GPIO)	0 / 1	0
	General Purpose I/O	8 / 8	8
A-B	SMBus	1/1	1
A-B	I2C	1 / 1	1
A-B	Watchdog Timer	0 / 1	1
A-B	Speaker Out	1/1	1
A-B	External BIOS ROM Support	0 / 2	1
A-B	Reset Functions	1 / 1	1
A-B		Power Managem	
A-B	Thermal Protection	0 / 1	1
A-B	Battery Low Alarm	0 / 1	1
A-B	Suspend/Wake Signals	0/3	1
A-B	Power Button Support	1/1	1
A-B	Power Good	1 / 1	1
A-B	VCC_5V_SBY Contacts	4 / 4	4
A-B <sup>1</sup>	Sleep Input	0 / 1	1
A-B <sup>1</sup>	Lid Input	0 / 1	1
A-B <sup>1</sup>	Fan Control Signals	0 / 2	2
A-B	Trusted Platform Modules	0 / 1	1
A-B		Power	
A-B	VCC 12V Contacts	12 / 12	12

Module Pin-out - Required and Optional Features C-D Connector. PICMG® COM.0 Revision 2.1

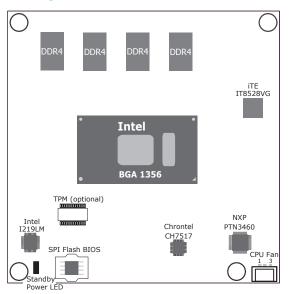
Connector	Feature	COM Express Module Base Specification Type 6 (No IDE or PCI, add DDI+ USB3) Min / Max	DFI KU968 Type 6
C-D		System I/O	
	PCI Express Lanes 16 - 31	0 / 16	0
	PCI Express Graphics (PEG)	0 / 1	0
C-D <sup>2</sup>	Muxed SDVO Channels 1 - 2	NA	NA
	PCI Express Lanes 6 - 15	0 / 2	2
	PCI Bus - 32 Bit	NA	NA
	PATA Port	NA	NA
	LAN Ports 1 - 2	NA	NA
	DDIs 1 - 3	0/3	1/2 (Option: DDI2 or VGA)
C-D <sup>2</sup>	USB 3.0 Ports	0 / 4	4
C-D		Power	
C-D	VCC_12V Contacts	12 / 12	12

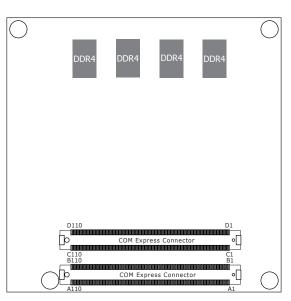
- 1 Indicates 12V-tolerant features on former VCC\_12V signals.
- 2 Cells in the connected columns spanning rows provide a rough approximation of features sharing connector pins.

Chapter 2 Concept www.dfi.com

## **Chapter 3 - Hardware Installation**

## **Board Layout**





Top View

Bottom View



#### Important:

Electrostatic discharge (ESD) can damage your board, processor, disk drives, add-in boards, and other components. Perform installation procedures at an ESD workstation only. If such a station is not available, you can provide some ESD protection by wearing an antistatic wrist strap and attaching it to a metal part of the system chassis. If a wrist strap is unavailable, establish and maintain contact with the system chassis throughout any procedures requiring ESD protection.

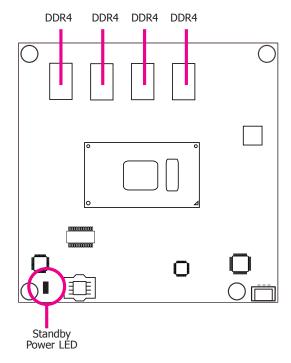
## **System Memory**

The system board is equipped with 16GB DDR4 system memory onboard supporting 2133MHz, dual channel memory interface.

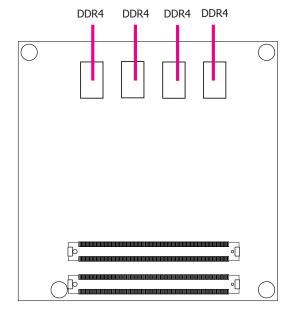


#### Important:

When the Standby Power LED is red, it indicates that there is power on the board. Power-off the PC then unplug the power cord prior to installing any devices. Failure to do so will cause severe damage to the board and components.



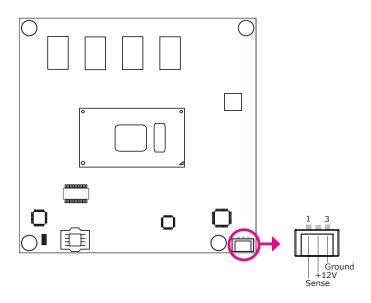
Top View



**Bottom View** 

#### **Connectors**

#### **CPU Fan Connector**



Connect the CPU fan's cable connector to the CPU fan connector on the board. The cooling fan will provide adequate airflow throughout the chassis to prevent overheating the CPU and board components.

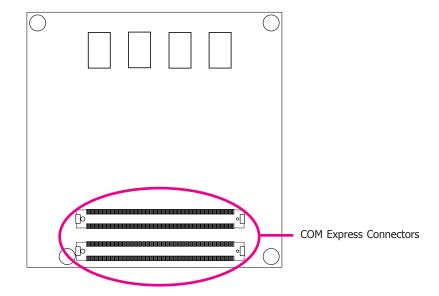
#### **BIOS Setting**

"PC Health Status" submenu in the Advanced menu of the BIOS will display the current speed of the cooling fan. Refer to chapter 4 of the manual for more information.

## **COM Express Connectors**

The COM Express connectors are used to interface the KU968 COM Express board to a carrier board. Connect the COM Express connectors (located on the solder side of the board) to the COM Express connectors on the carrier board.

Refer to the "Installing KU968 onto a Carrier Board" section in this chapter for more information



Refer to the following pages for the pin functions of these connectors.

## **COM Express Connectors**

Row A		Row B	1	Row A		Row B	1
A1	GND (FIXED)	B1	GND (FIXED)	A56	PCIE_TX4-	B56	PCIE_RX4-
A2	GBE0_MDI3-	B2	GBE0_ACT#	A57	GND	B57	GPO2
A3	GBE0_MDI3+	B3	LPC_FRAME#	A58	PCIE_TX3+	B58	PCIE_RX3+
A4	GBE0_LINK100#	B4	LPC_AD0	A59	PCIE_TX3-	B59	PCIE_RX3-
A5	GBE0 LINK1000#	B5	LPC_AD1	A60	GND (FIXED)	B60	GND (FIXED)
A6	GBE0_MDI2-	В6	LPC_AD2	A61	PCIE_TX2+	B61	PCIE_RX2+
A7	GBE0 MDI2+	В7	LPC AD3	A62	PCIE TX2-	B62	PCIE RX2-
A8	GBE0 LINK#	B8	LPC_DRQ0#	A63	GPI1	B63	GPO3
A9	GBE0 MDI1-	В9	LPC DRQ1#	A64	PCIE TX1+	B64	PCIE RX1+
A10	GBE0 MDI1+	B10	LPC CLK	A65	PCIE TX1-	B65	PCIE RX1-
A11	GND (FIXED)	B11	GND (FIXED)	A66	GND	B66	WAKE0#
A12	GBE0 MDI0-	B12	PWRBTN#	A67	GPI2	B67	WAKE1#
A13	GBE0 MDI0+	B13	SMB CK	A68	PCIE TX0+	B68	PCIE RX0+
A14	GBE0 CTREF	B14	SMB DAT	A69	PCIE TX0-	B69	PCIE RX0-
A15	SUS S3#	B15	SMB ALERT#	A70	GND (FIXED)	B70	GND (FIXED)
A16	SATA0 TX+	B16	SATA1 TX+	A71	LVDS A0+	B71	LVDS B0+
A17	SATA0_TX+	B17	SATA1_TX+	A72	LVDS_A0+	B72	LVDS_B0-
					_		
A18 A19	SUS_S4# SATA0 RX+	B18 B19	SUS_STAT# SATA1 RX+	A73 A74	LVDS_A1+ LVDS A1-	B73 B74	LVDS_B1+ LVDS_B1-
A19 A20		B20	_		_	_	LVDS_B1- LVDS B2+
	SATA0_RX-		SATA1_RX-	A75	LVDS_A2+	B75	
A21	GND (FIXED)	B21	GND (FIXED)	A76	LVDS_A2-	B76	LVDS_B2-
A22	SATA2_TX+	B22	NA	A77	LVDS_VDD_EN	B77	LVDS_B3+
A23	SATA2_TX-	B23	NA	A78	LVDS_A3+	B78	LVDS_B3-
A24	SUS_S5#	B24	PWR_OK	A79	LVDS_A3-	B79	LVDS_BKLT_EN
A25	SATA2_RX+	B25	NA	A80	GND (FIXED)	B80	GND (FIXED)
A26	SATA2_RX-	B26	NA	A81	LVDS_A_CK+	B81	LVDS_B_CK+
A27	BATLOW#	B27	WDT	A82	LVDS_A_CK-	B82	LVDS_B_CK-
A28	(S)ATA_ACT#	B28	NA	A83	LVDS_I2C_CK	B83	LVDS_BKLT_CTRL
A29	AC/HDA_SYNC	B29	AC/HDA _SDIN1	A84	LVDS_I2C_DAT	B84	VCC_5V_SBY
A30	AC/HDA _RST#	B30	AC/HDA _SDIN0	A85	GPI3	B85	VCC_5V_SBY
A31	GND (FIXED)	B31	GND (FIXED)	A86	RSVD	B86	VCC_5V_SBY
A32	AC/HDA _BITCLK	B32	SPKR	A87	RSVD	B87	VCC_5V_SBY
A33	AC/HDA _SDOUT	B33	I2C_CK	A88	PCIE0_CLK_REF+	B88	BIOS_DIS1#
A34	BIOS_DIS0#	B34	I2C_DAT	A89	PCIE0_CLK_REF-	B89	VGA_RED
A35	THRMTRIP#	B35	THRM#	A90	GND (FIXED)	B90	GND (FIXED)
A36	USB6-	B36	USB7-	A91	SPI_POWER	B91	VGA_GRN
A37	USB6+	B37	USB7+	A92	SPI_MISO	B92	VGA_BLU
A38	USB_6_7_OC#	B38	USB_4_5_OC#	A93	GPO0	B93	VGA_HSYNC
A39	USB4-	B39	USB5-	A94	SPI_CLK	B94	VGA_VSYNC
A40	USB4+	B40	USB5+	A95	SPI_MOSI	B95	VGA_I2C_CK
A41	GND (FIXED)	B41	GND (FIXED)	A96	NA	B96	VGA_I2C_DAT
A42	USB2-	B42	USB3-	A97	TYPE10#	B97	SPI_CS#
A43	USB2+	B43	USB3+	A98	SER0_TX	B98	RSVD
A44	USB_2_3_OC#	B44	USB_0_1_OC#	A99	SER0_RX	B99	RSVD
A45	USB0-	B45	USB1-	A100	GND (FIXED)	B100	GND (FIXED)
A46	USB0+	B46	USB1+	A101	SER1_TX	B101	FAN_PWMOUT
A47	VCC_RTC	B47	EXCD1_PERST#	A102	SER1_RX	B102	FAN_TACHIN
A48	EXCD0_PERST#	B48	EXCD1_CPPE#	A103	LID#	B103	SLEEP#
A49	EXCD0_CPPE#	B49	SYS_RESET#	A104	VCC_12V	B104	VCC_12V
A50	LPC_SERIRQ	B50	CB_RESET#	A105	VCC_12V	B105	VCC_12V
A51	GND (FIXED)	B51	GND (FIXED)	A106	VCC 12V	B106	VCC 12V
A52	PCIE TX5+	B52	PCIE RX5+	A107	VCC 12V	B107	VCC 12V
A53	PCIE TX5-	B53	PCIE RX5-	A108	VCC 12V	B108	VCC 12V
A54	GPI0	B54	GP01	A109	VCC 12V	B109	VCC_12V
A55	PCIE_TX4+	B55	PCIE_RX4+	A110	GND (FIXED)	B110	GND (FIXED)
					. ( /	1	

Row C	<u> </u>	Row D		Row C	;	Row D	)
C1	GND (FIXED)	D1	GND (FIXED)	C56	NA	D56	NA
C2	GND	D2	GND	C57	TYPE1#	D57	TYPE2#
C3	USB_SSRX0-	D3	USB SSTX0-	C58	NA	D58	NA
C4	USB SSRX0+	D4	USB SSTX0+	C59	NA	D59	NA
C5	GND	D5	GND	C60	GND (FIXED)	D60	GND (FIXED)
C6	USB SSRX1-	D6	USB SSTX1-	C61	NA	D61	NA
C7	USB SSRX1+	D7	USB SSTX1+	C62	NA	D62	NA
C8	GND	D8	GND	C63	RSVD	D63	RSVD
C9	USB_SSRX2-	D9	USB_SSTX2-	C64	RSVD	D64	RSVD
C10	USB_SSRX2+	D10	USB_SSTX2+	C65	NA	D65	NA
C11	GND (FIXED)	D11	GND (FIXED)	C66	NA	D66	NA
C12	USB_SSRX3-	D12	USB_SSTX3-	C67	RSVD	D67	GND
C13	USB_SSRX3+	D13	USB_SSTX3+	C68	NA	D68	NA
C14	GND	D14	GND	C69	NA	D69	NA
C15	NA	D15	DDI1_CTRLCLK_AUX+	C70	GND (FIXED)	D70	GND (FIXED)
C16	NA	D16	DDI1_CTRLDATA_AUX-	C71	NA	D71	NA
C17	RSVD	D17	RSVD	C72	NA	D72	NA
C18	RSVD	D18	RSVD	C73	GND	D73	GND
C19	PCIE RX6+	D19	PCIE TX6+	C74	NA	D74	NA
C20	PCIE RX6-	D20	PCIE TX6-	C75	NA	D75	NA
C21	GND (FIXED)	D21	GND (FIXED)	C76	GND	D76	GND
C22	PCIE RX7+	D22	PCIE TX7+	C77	RSVD	D77	RSVD
C23	PCIE RX7-	D23	PCIE TX7-	C78	NA	D78	NA
C24	DDI1 HPD	D24	RSVD	C79	NA	D79	NA
C25	NA	D25	RSVD	C80	GND (FIXED)	D80	GND (FIXED)
C26	NA	D26	DDI1_PAIR0+	C81	NA	D81	NA
C27	RSVD	D27	DDI1 PAIR0-	C82	NA	D82	NA
C28	RSVD	D28	RSVD	C83	RSVD	D83	RSVD
C29	NA NA	D29	DDI1 PAIR1+	C84	GND	D84	GND
C30	NA	D30	DDI1 PAIR1-	C85	NA	D85	NA
C31	GND (FIXED)	D31	GND (FIXED)	C86	NA	D86	NA
C32	DDI2_CTRLCLK_AUX+	D32	DDI1_PAIR2+	C87	GND	D87	GND
C33	DDI2_CTRLDATA_AUX-	D33	DDI1_PAIR2-	C88	NA	D88	NA
C34	DDI2_DDC_AUX_SEL	D34	DDI1_DDC_AUX_SEL	C89	NA	D89	NA
C35	RSVD	D35	RSVD	C90	GND (FIXED)	D90	GND (FIXED)
C36	NA	D36	DDI1_PAIR3+	C91	NA	D91	NA
C37	NA	D37	DDI1 PAIR3-	C92	NA	D92	NA
C38	NA	D38	RSVD	C93	GND	D93	GND
C39	NA	D39	DDI2 PAIR0+	C94	NA	D94	NA
C40	NA	D40	DDI2 PAIR0-	C95	NA	D95	NA
C41	GND (FIXED)	D41	GND (FIXED)	C96	GND	D96	GND
C42	NA	D42	DDI2_PAIR1+	C97	RSVD	D97	RSVD
C43	NA	D43	DDI2_PAIR1-	C98	NA	D98	NA
C44	NA	D44	DDI2 HPD	C99	NA	D99	NA
C45	RSVD	D45	RSVD	C100	GND (FIXED)	D100	GND (FIXED)
C46	NA	D46	DDI2_PAIR2+	C101	NA	D101	NA
C47	NA	D47	DDI2 PAIR2-	C102	NA	D102	NA
C48	RSVD	D48	RSVD	C103	GND	D103	GND
C49	NA	D49	DDI2 PAIR3+	C104	VCC 12V	D104	VCC 12V
C50	NA	D50	DDI2 PAIR3-	C105	VCC 12V	D105	VCC_12V
C51	GND (FIXED)	D51	GND (FIXED)	C106	VCC_12V	D106	VCC 12V
C52	NA	D52	NA	C107	VCC 12V	D107	VCC 12V
C53	NA	D53	NA	C108	VCC 12V	D108	VCC_12V
C54	TYPE0#	D54	PEG LANE RV#	C109	VCC 12V	D109	VCC 12V
C55	NA	D55	NA	C110	GND (FIXED)	D110	GND (FIXED)
		1-20			(,)	1	()

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## **COM Express Connectors Signals and Descriptions**

- Pin Types
  I Input to the Module
  O Output from the Module
  I/O Bi-directional input / output signal
  OD Open drain output

AC97/HDA Signals Descriptions							
Signal	Pin#	Module Pin Type	Pwr Rail / Tolerance	KU968	Carrier Board	Description	
AC/HDA_RST#	A30	O CMOS	3.3V Suspend/3.3V		Connect to CODEC pin 11 RESET#	Reset output to CODEC, active low.	
AC/HDA_SYNC	A29	O CMOS	3.3V/3.3V		Connect to CODEC pin 10 SYNC	Sample-synchronization signal to the CODEC(s).	
AC/HDA_BITCLK	A32	I/O CMOS	3.3V/3.3V		Connect to CODEC pin 6 BIT_CLK	Serial data clock generated by the external CODEC(s).	
AC/HDA_SDOUT	A33	O CMOS	3.3V/3.3V		Connect to CODEC pin 5 SDATA_OUT	Serial TDM data output to the CODEC.	
AC/HDA_SDIN2	B28	I/O CMOS	3.3V Suspend/3.3V	NA			
AC/HDA_SDIN1	B29	I/O CMOS	3.3V Suspend/3.3V			Serial TDM data inputs from up to 2 CODECs.	
AC/HDA_SDIN0	B30	I/O CMOS	3.3V Suspend/3.3V		Connect 33 Ω in series to CODEC0 pin 8 SDATA_IN		

Gigabit Ethernet Signals Descriptions							
Signal	Pin#	Module Pin Type	Pwr Rail / Tolerance KU968	Carrier Board	Description		
GBE0_MDI0+	A13	I/O Analog	3.3V max Suspend	Connect to Magnetics Module MDI0+/-	Gigabit Ethernet Controller 0: Media Dependent Interface Differential Pairs 0,1,2,3. The MDI can operate in 1000, 100 and 10 Mbit / sec modes. Some pairs are unused in some modes, per the following:  1000BASE-T 100BASE-TX 10BASE-TX  MDI[0]+/- B1_DA+/- TX+/- TX+/-  MDI[1]+/- B1_DB+/- RX+/- RX+/-  MDI[2]+/- B1_DC+/-  MDI[3]+/- B1_DD+/-		
GBE0_MDI0-	A12	I/O Analog	3.3V max Suspend				
GBE0_MDI1+	A10	I/O Analog	3.3V max Suspend	Connect to Magnetics Module MDI1+/-			
GBE0_MDI1-	A9	I/O Analog	3.3V max Suspend				
GBE0_MDI2+	A7	I/O Analog	3.3V max Suspend	Connect to Magnetics Module MDI2+/-			
GBE0_MDI2-	A6	I/O Analog	3.3V max Suspend				
GBE0_MDI3+	A3	I/O Analog	3.3V max Suspend	Connect to Magnetics Module MDI3+/-			
GBE0_MDI3-	A2	I/O Analog	3.3V max Suspend				
GBE0_ACT#	B2	OD CMOS	3.3V Suspend/3.3V	Connect to LED and <b>recommend</b> current limit resistor 150 $\Omega$ to 3.3VSB	Gigabit Ethernet Controller 0 activity indicator, active low.		
GBE0_LINK#	A8	OD CMOS	3.3V Suspend/3.3V	NC	Gigabit Ethernet Controller 0 link indicator, active low.		
GBE0 LINK100#	A4	OD CMOS	3.3V Suspend/3.3V	Connect to LED and <b>recommend</b> current limit resistor 150 $\Omega$ to 3.3VSB	Gigabit Ethernet Controller 0 100 Mbit / sec link indicator, active low.		
GBE0_LINK1000#	A5	OD CMOS	3.3V Suspend/3.3V	Connect to LED and <b>recommend</b> current limit resistor 150 $\Omega$ to 3.3VSB	Gigabit Ethernet Controller 0 1000 Mbit / sec link indicator, active low.		

SATA Signals Descript	tions					
Signal	Pin#	Module Pin Type	Pwr Rail / Tolerance	KU968	Carrier Board	Description
SATA0_TX+	A16	O SATA	AC coupled on Module	AC Coupling capacitor	Connect to SATAO Conn TX pin	Serial ATA or SAS Channel 0 transmit differential pair.
SATA0_TX-	A17	O SATA	AC coupled on Module	AC Coupling capacitor	Connect to SATAO CONTENT DIN	Serial ATA OF SAS Channel O transmit differential pair.
SATA0_RX+	A19	I SATA	AC coupled on Module	AC Coupling capacitor	-Connect to SATAO Conn RX pin	Serial ATA or SAS Channel 0 receive differential pair.
SATA0_RX-	A20	I SATA	AC coupled on Module	AC Coupling capacitor	Connect to SATAO Conn to pin	Serial ATA of SAS charifier of receive differential pair.
SATA1_TX+	B16	O SATA	AC coupled on Module	AC Coupling capacitor	Connect to SATA1 Conn TX pin	Serial ATA or SAS Channel 1 transmit differential pair.
SATA1_TX-	B17	O SATA	AC coupled on Module	AC Coupling capacitor	Connect to SATAT CONTITA pin	Serial ATA OF SAS Chamiler 1 dansmit differential pair.
SATA1_RX+	B19	I SATA	AC coupled on Module	AC Coupling capacitor	Connect to SATA1 Conn RX pin	Serial ATA or SAS Channel 1 receive differential pair.
SATA1_RX-	B20	I SATA	AC coupled on Module	AC Coupling capacitor	Connect to SATAT Conn to pin	Serial ATA of SAS chariffer 1 receive differential pair.
SATA2_TX+	A22	O SATA	AC coupled on Module	AC Coupling capacitor	Connect to SATA2 Conn TX pin	Serial ATA or SAS Channel 2 transmit differential pair.
SATA2_TX-	A23	O SATA	AC coupled on Module	AC Coupling capacitor	CONNECT TO SATIAL CONN TA PIN	Schar ATA Or SAS channel 2 dansmit american pair.
SATA2_RX+	A25	I SATA	AC coupled on Module	AC Coupling capacitor	Connect to SATA2 Conn RX pin	Serial ATA or SAS Channel 2 receive differential pair.
SATA2_RX-	A26	I SATA	AC coupled on Module	AC Coupling capacitor	CONNECT TO SATAL CONN FOR PIN	Schar ATA or SAS charmer 2 receive american pair.
SATA3_TX+	B22	O SATA	AC coupled on Module	NA		Serial ATA or SAS Channel 3 transmit differential pair.
SATA3_TX-	B23	O SATA	AC coupled on Module	NA		Serial ATA OF SAS Chamiler 5 danismic differential pair.
SATA3_RX+	B25	I SATA	AC coupled on Module	NA		Serial ATA or SAS Channel 3 receive differential pair.
SATA3_RX-	B26	I SATA	AC coupled on Module	NA		·
(S)ATA_ACT#	A28	I/O CMOS	3.3V / 3.3V	PU 10K to 3.3V	Connect to LED and <b>recommend</b> current limit resistor 220Ω to 3.3V	ATA (parallel and serial) or SAS activity indicator, active low.

PCI Express Lanes Signals Descriptions									
Signal	Pin#	Module Pin Type	Pwr Rail / Tolerance	KU968	Carrier Board	Description			
PCIE_TX0+	A68	O PCIE	AC coupled on Module	AC Coupling capacitor	Connect to PCIE device or slot	PCI Express Differential Transmit Pairs 0			
PCIE_TX0-	A69	O PCIL	AC Coupled on Module	AC Coupling capacitor	Conflict to rate device of Siot	red Express Differential Harismit rails 0			
PCIE_RX0+	B68	I PCIE	AC coupled off Module		Device - Connect AC Coupling cap 0.1uF	PCI Express Differential Receive Pairs 0			
PCIE_RX0-	B69	I PCIE	AC coupled oil Module		Slot - Connect to PCIE Conn pin	PCI Express Differential Receive Pails 0			
PCIE_TX1+	A64	O PCIE	AC coupled on Module	AC Coupling capacitor	Connect to PCIE device or slot	PCI Express Differential Transmit Pairs 1			
PCIE_TX1-	A65	O PCIE	AC coupled on Module	AC Coupling capacitor	Connect to PCIE device or Siot	PCI Express Differential Transmit Pails 1			
PCIE_RX1+	B64	I PCIE	AC coupled off Module		Device - Connect AC Coupling cap 0.1uF	PCI Express Differential Receive Pairs 1			
PCIE_RX1-	B65	I PCIE	AC coupled oil Module		Slot - Connect to PCIE Conn pin	PCI Express Differential Receive Pairs 1			

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PCI Express Lanes Signals Descriptions								
Signal	Pin#	Module Pin Type	Pwr Rail / Tolerance	KU968	Carrier Board	Description		
PCIE_TX2+ PCIE_TX2-	A61 A62	O PCIE	AC coupled on Module	AC Coupling capacitor AC Coupling capacitor	Connect to PCIE device or slot	PCI Express Differential Transmit Pairs 2		
PCIE_RX2+ PCIE_RX2-	B61 B62	I PCIE	AC coupled off Module		Device - Connect AC Coupling cap 0.1uF Slot - Connect to PCIE Conn pin	PCI Express Differential Receive Pairs 2		
PCIE_TX3+ PCIE_TX3-	A58 A59	O PCIE	AC coupled on Module	AC Coupling capacitor AC Coupling capacitor	Connect to PCIE device or slot	PCI Express Differential Transmit Pairs 3		
PCIE_RX3+ PCIE_RX3-	B58 B59	I PCIE	AC coupled off Module		Device - Connect AC Coupling cap 0.1uF Slot - Connect to PCIE Conn pin	PCI Express Differential Receive Pairs 3		
PCIE_TX4+ PCIE_TX4-	A55 A56	O PCIE	AC coupled on Module	AC Coupling capacitor AC Coupling capacitor	Connect to PCIE device or slot	PCI Express Differential Transmit Pairs 4		
PCIE_RX4+ PCIE_RX4-	B55 B56	I PCIE	AC coupled off Module		Device - Connect AC Coupling cap 0.1uF Slot - Connect to PCIE Conn pin	PCI Express Differential Receive Pairs 4		
PCIE_TX5+ PCIE_TX5-	A52 A53	O PCIE	AC coupled on Module	AC Coupling capacitor AC Coupling capacitor	Connect to PCIE device or slot	PCI Express Differential Transmit Pairs 5		
PCIE_RX5+ PCIE_RX5-	B52 B53	I PCIE	AC coupled off Module		Device - Connect AC Coupling cap 0.1uF Slot - Connect to PCIE Conn pin	PCI Express Differential Receive Pairs 5		
PCIE_TX6+ PCIE_TX6-	D19 D20	O PCIE	AC coupled on Module	AC Coupling capacitor AC Coupling capacitor	Connect to PCIE device or slot	PCI Express Differential Transmit Pairs 6		
PCIE_RX6+ PCIE_RX6-	C19 C20	I PCIE	AC coupled off Module		Device - Connect AC Coupling cap 0.1uF Slot - Connect to PCIE Conn pin	PCI Express Differential Receive Pairs 6		
PCIE_TX7+ PCIE_TX7-	D22 D23	O PCIE	AC coupled on Module	AC Coupling capacitor AC Coupling capacitor	Connect to PCIE device or slot	PCI Express Differential Transmit Pairs 7		
PCIE_RX7+ PCIE_RX7-	C22 C23	I PCIE	AC coupled off Module		Device - Connect AC Coupling cap 0.1uF Slot - Connect to PCIE Conn pin	PCI Express Differential Receive Pairs 7		
PCIEO_CLK_REF+ PCIEO CLK REF-	A88 A89	O PCIE	PCIE		Connect to PCIE device, <b>PCIe CLK Buffer</b> or slot	Reference clock output for all PCI Express and PCI Express Graphics lanes.		
		,			•			

PEG Signals Descriptions										
Signal	Pin#	Module Pin Type	Pwr Rail / Tolerance	KU968	Carrier Board	Description				
PEG_TX0+	D52	O PCIE	AC coupled on Module	NA		PCI Express Graphics transmit differential pairs 0				
PEG_TX0-	D53	0.012	ne coapiea on riodale	NA		. S. Z. Sp. ess Graphics datasing an action pairs o				
PEG_RX0+ PEG_RX0-	C52 C53	I PCIE	AC coupled off Module	NA NA		PCI Express Graphics receive differential pairs 0				
PEG_KXU- PEG_TX1+	D55		1	NA NA						
PEG_TX1-	D56	O PCIE	AC coupled on Module	NA NA	-	PCI Express Graphics transmit differential pairs 1				
PEG_RX1+	C55			NA						
PEG RX1-	C56	I PCIE	AC coupled off Module	NA		PCI Express Graphics receive differential pairs 1				
PEG_TX2+	D58	O PCIE	AC coupled on Module	NA		PCI Express Graphics transmit differential pairs 2				
PEG_TX2-	D59	OFCIL	Ac coupled on Floudie	NA		rea express draphics transmit unrerential pairs 2				
PEG_RX2+	C58	I PCIE	AC coupled off Module	NA		PCI Express Graphics receive differential pairs 2				
PEG_RX2-	C59			NA						
PEG_TX3+ PEG_TX3-	D61 D62	O PCIE	AC coupled on Module	NA NA		PCI Express Graphics transmit differential pairs 3				
PEG_RX3+	C61			NA NA						
PEG_RX3-	C62	I PCIE	AC coupled off Module	NA NA		PCI Express Graphics receive differential pairs 3				
PEG_TX4+	D65			NA NA						
PEG_TX4-	D66	O PCIE	AC coupled on Module	NA	1	PCI Express Graphics transmit differential pairs 4				
PEG_RX4+	C65	I PCIE	AC coupled off Module	NA		PCI Express Graphics receive differential pairs 4				
PEG_RX4-	C66	I FCIL	Ac coupled on Plodule	NA		rea express diapriles receive uniferential pairs 4				
PEG_TX5+	D68	O PCIE	AC coupled on Module	NA		PCI Express Graphics transmit differential pairs 5				
PEG_TX5-	D69 C68			NA						
PEG_RX5+ PEG_RX5-	C69	I PCIE	AC coupled off Module	NA NA		PCI Express Graphics receive differential pairs 5				
PEG_TX6+	D71							NA NA		
PEG_TX6-	D72	O PCIE	AC coupled on Module	NA NA		PCI Express Graphics transmit differential pairs 6				
PEG_RX6+	C71	I DOIE	10 11 61	NA		DOTE OF IT IN THE COLUMN				
PEG_RX6-	C72	I PCIE	AC coupled off Module	NA		PCI Express Graphics receive differential pairs 6				
PEG_TX7+	D74	O PCIE	AC coupled on Module	NA		PCI Express Graphics transmit differential pairs 7				
PEG_TX7-	D75	OTCL	Ac coupled on Floudic	NA		1 CE Express Graphics durishing differential pairs 7				
PEG_RX7+	C74	I PCIE	AC coupled off Module	NA		PCI Express Graphics receive differential pairs 7				
PEG_RX7- PEG_TX8+	C75 D78	-		NA NA						
PEG_TX8+	D78	O PCIE	AC coupled on Module	NA NA	-	PCI Express Graphics transmit differential pairs 8				
PEG_RX8+	C78			NA NA						
PEG_RX8-	C79	I PCIE	AC coupled off Module	NA		PCI Express Graphics receive differential pairs 8				
PEG_TX9+	D81	O PCIE	AC seconded on Medicals	NA		DCI Fusiona Combinatorio di Stato della Compania di Stato di Compania di Stato di Compania				
PEG_TX9-	D82	UPCIE	AC coupled on Module	NA		PCI Express Graphics transmit differential pairs 9				
PEG_RX9+	C81	I PCIE	AC coupled off Module	NA		PCI Express Graphics receive differential pairs 9				
PEG_RX9-	C82	- 1 011	III pica on Floatic	NA						
PEG_TX10+	D85	O PCIE	AC coupled on Module	NA		PCI Express Graphics transmit differential pairs 10				
PEG_TX10- PEG_RX10+	D86 C85			NA NA						
PEG_RX10+ PEG_RX10-	C86	I PCIE	AC coupled off Module	NA NA	-	PCI Express Graphics receive differential pairs 10				
PEG_TX11+	D88			NA NA						
PEG_TX11-	D89	O PCIE	AC coupled on Module	NA NA	1	PCI Express Graphics transmit differential pairs 11				
PEG_RX11+	C88	I PCIE	AC	NA		POT Frances Complies associated differential point 11				
PEG_RX11-	C89	1 PCIE	AC coupled off Module	NA		PCI Express Graphics receive differential pairs 11				
LEG_KVII-	109		1	IVA						

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PEG Signals Descriptions						
Signal	Pin#	Module Pin Type	Pwr Rail / Tolerance	KU968	Carrier Board	Description
PEG_TX12+	D91	O PCIE	AC coupled on Module	NA NA		PCI Express Graphics transmit differential pairs 12
PEG_TX12- PEG_RX12+	D92 C91		'	NA NA		
PEG_RX12+	C92	I PCIE	AC coupled off Module	NA NA		PCI Express Graphics receive differential pairs 12
PEG_TX13+	D94			NA NA		
PEG_TX13-	D95	O PCIE	AC coupled on Module	NA		PCI Express Graphics transmit differential pairs 13
PEG_RX13+	C94	I PCIE	AC coupled off Module	NA		PCI Express Graphics receive differential pairs 13
PEG_RX13-	C95	I FCIL	Ac coupled on Floudie	NA		PCI Express diaphics receive differential pails 15
PEG_TX14+	D98	O PCIE	AC coupled on Module	NA NA		PCI Express Graphics transmit differential pairs 14
PEG_TX14-	D99			NA NA		The second secon
PEG_RX14+ PEG_RX14-	C98 C99	I PCIE	AC coupled off Module	NA NA	-	PCI Express Graphics receive differential pairs 14
PEG_TX15+	D101			NA NA		
PEG_TX15-	D102	O PCIE	AC coupled on Module	NA NA		PCI Express Graphics transmit differential pairs 15
PEG_RX15+	C101	I PCIE	AC	NA		PCI France Combine and differential anim 15
PEG_RX15-	C102	I PCIE	AC coupled off Module	NA		PCI Express Graphics receive differential pairs 15
PEG_LANE_RV#	D54	I CMOS	3.3V / 3.3V	PU 10K to 3.3V		PCI Express Graphics lane reversal input strap. Pull low on the Carrier
PEG_LAINE_RV#	D34	1 CMOS	3.34 / 3.34	PO 10K to 3.5V		board to reverse lane order.
ExpressCard Signals Descri	iptions					
Signal	Pin#	Module Pin Type	Pwr Rail / Tolerance	KU968	Carrier Board	Description
EXCD0_CPPE#	A49	I CMOS	3.3V / 3.3V	PU 10k to 3.3V		PCI ExpressCard: PCI Express capable card request, active low, one per
EXCD1_CPPE#	B48 A48			PU 10k to 3.3V		card
EXCD0_PERST# EXCD1 PERST#	A48 B47	O CMOS	3.3V / 3.3V		-	PCI ExpressCard: reset, active low, one per card
EXCDI_FER31#	D47			1		
<b>DDI Signals Descriptions</b>						
Signal	Pin#	Module Pin Type	Pwr Rail / Tolerance	KU968	Carrier Board	Description
DDI1_PAIR0+/SDVO1_RED+	D26				Connect AC Coupling Capacitors 0.1uF to Device	
DDI1_PAIR0-/SDVO1_RED-	D27	O PCIE	AC coupled off Module		Connect AC Coupling Capacitors 0.1uF to Device	DDI 1 Pair 0 differential pairs/Serial Digital Video B red output differential pair
DDI1_PAIR1+/SDVO1_GRN+	D29	O PCIE	AC coupled off Module		Connect AC Coupling Capacitors 0.1uF to Device	DDI 1 Pair 1 differential pairs/Serial Digital Video B green output differential pair
DDI1_PAIR1-/SDVO1_GRN-	D30				Connect AC Coupling Capacitors 0.1uF to Device	
DDI1_PAIR2+/SDVO1_BLU+ DDI1_PAIR2-/SDVO1_BLU-	D32 D33	O PCIE	AC coupled off Module		Connect AC Coupling Capacitors 0.1uF to Device	DDI 1 Pair 2 differential pairs/Serial Digital Video B blue output differential pair
DDI1_PAIR2-/SDV01_BL0- DDI1_PAIR3+/SDV01_CK+	D36				Connect AC Coupling Capacitors 0.1uF to Device  Connect AC Coupling Capacitors 0.1uF to Device	
DDI1_PAIR3-/SDVO1_CK-	D37	O PCIE	AC coupled off Module		Connect AC Coupling Capacitors 0.1uF to Device	DDI 1 Pair 3 differential pairs/Serial Digital Video B clock output differential pair
DDI1_PAIR4+/SDVO1_INT+	C25	T DOTE	10 11 64 11	NA	connect the coupling expectate of the period	
DDI1_PAIR4-/SDVO1_INT-	C25 C26	I PCIE	AC coupled off Module	NA		Serial Digital Video B interrupt input differential pair.
DDI1_PAIR5+/SDVO1_TVCLKIN+	C29	I PCIE	AC coupled off Module	NA		Serial Digital Video TVOUT synchronization clock input differential pair.
DDI1_PAIR5-/SDVO1_TVCLKIN-	C30	11012	ric coupied on riodale	NA NA		Serial Signal video 17001 Synamonization about input directical pain.
DDI1_PAIR6+/SDV01_FLDSTALL+	C15	I PCIE	AC coupled off Module	NA NA		Serial Digital Video Field Stall input differential pair.
DDI1_PAIR6-/SDVO1_FLDSTALL-	C16			PD 100K to GND		
		I/O PCIE	AC coupled on Module	(S/W IC between Rpu/PCH)	Connect to DP AUX+	DP AUX+ function if DDI1_DDC_AUX_SEL is no connect
DDI1_CTRLCLK_AUX+/SDVO1_CTRLCLK	D15			PU 4.7K to 3.3V, PD 100K to GND		
DDII_CTRECER_AOX+/3DVOI_CTRECER	D13	T/O OD CMOS	OD CMOS 3.3V / 3.3V		Connect to HDMI/DVI I2C CTRLCLK	HDMI/DVI I2C CTRLCLK if DDI1_DDC_AUX_SEL is pulled high
		1/0 00 0103			Connect to FiDMI/DVI 12C CTRECER	
				PU 100K to 3.3V		
		I/O PCIE	AC coupled on Module	(S/W IC between Rpu/PCH)	Connect to DP AUX-	DP AUX- function if DDI1_DDC_AUX_SEL is no connect
DDI1_CTRLDATA_AUX-	D16			PU 4.7K to 3.3V/PU 100K to 3.3V		
/SDVO1_CTRLDATA	DIO	I/O OD CMOS	3.3V / 3.3V	(S/W IC between 4.7K/100K	Connect to HDMI/DVI I2C CTRLDATA	HDMI/DVI I2C CTRLDATA if DDI1_DDC_AUX_SEL is pulled high
		1/0 00 0103	3.34 / 3.34	resistor)	CONNECT TO FIDE THE CIRCLE ATA	INDIVIDUAL IZC CINEDATA II DDII_DDC_AOA_SEE IS pulled high
DDI1 LIDD	C24	I CMOC	2 21/ / 2 21/		DD 1M and Connect to desire 11st Dive Datest	DOT LIST DIVISION DISTRICT
DDI1_HPD	C24	I CMOS	3.3V / 3.3V		PD 1M and Connect to device Hot Plug Detect	DDI Hot-Plug Detect
						Selects the function of DDI1_CTRLCLK_AUX+ and DDI1_CTRLDATA_AUX
DDI1_DDC_AUX_SEL	D34	I CMOS	3.3V / 3.3V	PD 1M to GND	PU 100K to 3.3V for DDC(HDMI/DVI)	DDI[n]_DDC_AUX_SEL shall be pulled to 3.3V on the Carrier with a 100K Ohm
DDII_DDC_AOX_SEE	551	1 01103	3.54 / 3.54	TO IN to GND	1 0 100K to 5.54 for BBC(11B1-17B41)	resistor to configure the DDI[n]_AUX pair as the DDC channel.
	1		<u> </u>	<u> </u>		Carrier DDI[n]_DDC_AUX_SEL should be connected to pin 13 of the DisplayPort
DDI2_PAIR0+	D39	O PCIE	AC coupled off Module		Connect AC Coupling Capacitors 0.1uF to Device	DDI 2 Pair 0 differential pairs
DDI2_PAIR0-	D40	OTCIL	Ac coupied on Floduic		Connect AC Coupling Capacitors 0.1uF to Device	DDI 2 Tuli V directicul pulis
DDI2_PAIR1+	D42	O PCIE	AC coupled off Module		Connect AC Coupling Capacitors 0.1uF to Device	DDI 2 Pair 1 differential pairs
DDI2_PAIR1- DDI2_PAIR2+	D43 D46				Connect AC Coupling Capacitors 0.1uF to Device	· · · · · · · · · · · · · · · · · · ·
DDI2_PAIR2+ DDI2_PAIR2-	D47	O PCIE	AC coupled off Module		Connect AC Coupling Capacitors 0.1uF to Device  Connect AC Coupling Capacitors 0.1uF to Device	DDI 2 Pair 2 differential pairs
DDI2_PAIR3+	D49	o perr			Connect AC Coupling Capacitors 0.1uF to Device	PDY 2 D : 2 PW PL I
DDI2_PAIR3-	D50	O PCIE	AC coupled off Module		Connect AC Coupling Capacitors 0.1uF to Device	DDI 2 Pair 3 differential pairs
		I/O PCIE	AC coupled on Module	PD 100K to GND	Connect to DP AUX+	DP AUX+ function if DDI2_DDC_AUX_SEL is no connect
		1/O FCIL	AC Coupled on Flodule	(S/W IC between Rpu/PCH)	CONTINUE TO DE MONT	DI MONT TURCUOTTI DELE DEC MON DEE 19 110 COTTRECC
DDI2_CTRLCLK_AUX+	C32			PU 4.7K to 3.3V, PD 100K to GND		
		I/O OD CMOS	3.3V / 3.3V	(S/W IC between Rpu/Rpd	Connect to HDMI/DVI I2C CTRLCLK	HDMI/DVI I2C CTRLCLK if DDI2_DDC_AUX_SEL is pulled high
	1			resistor)		
		I/O PCIE	AC coupled on Module	PU 100K to 3.3V (S/W IC between Rpu/PCH)	Connect to DP AUX-	DP AUX- function if DDI2_DDC_AUX_SEL is no connect
DDI2_CTRLDATA_AUX-	C33			PU 4.7K to 3.3V/PU 100K to 3.3V		
		I/O OD CMOS	3.3V / 3.3V	(S/W IC between 4.7K/100K	Connect to HDMI/DVI I2C CTRLDATA	HDMI/DVI I2C CTRLDATA if DDI2_DDC_AUX_SEL is pulled high
				resistor)		

DDI Signals Descriptions						
Signal	Pin#	Module Pin Type	Pwr Rail / Tolerance	KU968	Carrier Board	Description
DDI2_HPD	D44	I CMOS	3.3V / 3.3V	KU900	PD 1M and Connect to device Hot Plug Detect	DDI Hot-Plug Detect
DDI2_DDC_AUX_SEL	C34	I CMOS	3.3V / 3.3V	PD 1M to GND	PU 100K to 3.3V for DDC(HDMI/DVI)	Selects the function of DDI2_CTRLCLK_AUX+ and DDI2_CTRLDATA_AUX DDI[n]_DDC_AUX_SEL shall be pulled to 3.3V on the Carrier with a 100K Ohm resistor to configure the DDI[n]_AUX_pair as the DDC channel. Carrier DDI[n]_DDC_AUX_SEL should be connected to pin 13 of the DisplayPort
DDI3_PAIR0+ DDI3_PAIR0-	C39 C40	O PCIE	AC coupled off Module	NA NA		DDI 3 Pair 0 differential pairs
DDI3_PAIR1+	C42	O PCIE	AC coupled off Module	NA NA		DDI 3 Pair 1 differential pairs
DDI3_PAIR1- DDI3_PAIR2+	C43 C46	O PCIE	AC coupled off Module	NA NA		DDI 3 Pair 2 differential pairs
DDI3_PAIR2- DDI3_PAIR3+	C47 C49			NA NA		
DDI3_PAIR3-	C50	O PCIE	AC coupled off Module	NA NA		DDI 3 Pair 3 differential pairs
DDI3_CTRLCLK_AUX+	C36	I/O PCIE	AC coupled on Module	NA		DP AUX+ function if DDI3_DDC_AUX_SEL is no connect
obio_emedat_nox1	230	I/O OD CMOS	3.3V / 3.3V	NA		HDMI/DVI I2C CTRLCLK if DDI3_DDC_AUX_SEL is pulled high
DDI3_CTRLDATA_AUX-	C37	I/O PCIE	AC coupled on Module	NA		DP AUX- function if DDI3_DDC_AUX_SEL is no connect
		I/O OD CMOS	3.3V / 3.3V	NA		HDMI/DVI I2C CTRLDATA if DDI3_DDC_AUX_SEL is pulled high
DDI3_HPD	C44	I CMOS	3.3V / 3.3V	NA		DDI Hot-Plug Detect
DDI3_DDC_AUX_SEL	C38	I CMOS	3.3V / 3.3V	NA		Selects the function of DDI3_CTRLCLK_AUX+ and DDI3_CTRLDATA_AUX DDI[n]_DDC_AUX_SEL shall be pulled to 3.3V on the Carrier with a 100K Ohm resistor to configure the DDI[n]_AUX pair as the DDC Channel. Carrier DDI[n]_DDC_AUX_SEL should be connected to pin 13 of the DisplayPort
<b>USB Signals Descriptions</b>	;					
Signal USB0+	Pin#	Module Pin Type	Pwr Rail / Tolerance	KU968	Carrier Board	Description
USB0+ USB0-	A46 A45	I/O USB	3.3V Suspend/3.3V		Connect 90 ♀ @100MHz Common Choke in series and ESD suppressors to GND to USB connector	USB differential pairs 0
USB1+	B46	I/O USB	3.3V Suspend/3.3V		Connect 90	USB differential pairs 1
USB1- USB2+	B45 A43	I/O USB	3.3V Suspend/3.3V		connector  Connect 90  @100MHz Common Choke in series and ESD suppressors to GND to USB	USB differential pairs 2
USB2- USB3+	A42 B43				connector  Connect 90 ♀ @100MHz Common Choke in series and ESD suppressors to GND to USB	, and the second
USB3-	B42	I/O USB	3.3V Suspend/3.3V		connector	USB differential pairs 3
USB4+ USB4-	A40 A39	I/O USB	3.3V Suspend/3.3V		Connect 90 \text{\Q} \text{\@}100MHz Common Choke in series and ESD suppressors to GND to USB connector	USB differential pairs 4
USB5+	B40	I/O USB	3.3V Suspend/3.3V		Connect 90	USB differential pairs 5
USB6+	B39 A37	I/O USB	3.3V Suspend/3.3V		connector  Connect 90 \( \Omega \) @100MHz Common Choke in series and ESD suppressors to GND to USB	USB differential pairs 6
USB6- USB7+	A36 B37		, ,		connector  Connect 90 ♀ @100MHz Common Choke in series and ESD suppressors to GND to USB	
USB7-	B36	I/O USB	3.3V Suspend/3.3V		connector	USB differential pairs 7
USB_0_1_OC#	B44	I CMOS	3.3V Suspend/3.3V	PU 10k to 3V3_DU	Connect to Overcurrent of USB Power Switch	USB over-current sense, USB channels 0 and 1. A pull-up for this line shall be present on the Module. An open drain driver from a USB current monitor on the Carrier Board may drive this line low. Do not pull this line high on the Carrier Board.
USB_2_3_OC#	A44	I CMOS	3.3V Suspend/3.3V	PU 10k to 3V3_DU	Connect to Overcurrent of USB Power Switch	USB over-current sense, USB channels 2 and 3. A pull-up for this line shall be present on the Module. An open drain driver from a USB current monitor on the Carrier Board may drive this line low. Do not pull this line high on the Carrier Board.
USB_4_5_OC#	B38	I CMOS	3.3V Suspend/3.3V	PU 10k to 3V3_DU	Connect to Overcurrent of USB Power Switch	USB over-current sense, USB channels 4 and 5. A pull-up for this line shall be present on the Module. An open drain driver from a USB current monitor on the Carrier Board may drive this line low. Do not pull this line high on the Carrier Board.
USB_6_7_OC#	A38	I CMOS	3.3V Suspend/3.3V	PU 10k to 3V3_DU	Connect to Overcurrent of USB Power Switch	USB over-current sense, USB channels 6 and 7. A pull-up for this line shall be present on the Module. An open drain driver from a USB current monitor on the Carrier Board may drive this line low. Do not pull this line high on the Carrier Board.
USB_SSTX0+ USB_SSTX0-	D4 D3	O PCIE	AC coupled on Module	AC Coupling capacitor AC Coupling capacitor	Connect 90 \to @100MHz Common Choke in series and ESD suppressors to GND to USB connector	Additional transmit signal differential pairs for the SuperSpeed USB data path.
USB_SSRX0+	C4	I PCIE	AC coupled off Module	assp.ing capacitor	Connect 90     @100MHz Common Choke in series and ESD suppressors to GND to USB	Additional receive signal differential pairs for the SuperSpeed USB data path.
USB_SSRX0- USB_SSTX1+	C3 D7	O PCIE		AC Coupling capacitor	connector  Connect 90  @100MHz Common Choke in series and ESD suppressors to GND to USB	
USB_SSTX1- USB_SSRX1+	D6 C7		AC coupled on Module	AC Coupling capacitor	connector Connect 90 \( \Omega \) @100MHz Common Choke in series and ESD suppressors to GND to USB	Additional transmit signal differential pairs for the SuperSpeed USB data path.
USB_SSRX1-	C6	I PCIE	AC coupled off Module		connector	Additional receive signal differential pairs for the SuperSpeed USB data path.
USB_SSTX2+ USB_SSTX2-	D10 D9	O PCIE	AC coupled on Module	AC Coupling capacitor AC Coupling capacitor	Connect 90 ♀ @100MHz Common Choke in series and ESD suppressors to GND to USB connector	Additional transmit signal differential pairs for the SuperSpeed USB data path.
USB_SSRX2+ USB_SSRX2-	C10 C9	I PCIE	AC coupled off Module	and any operator	Connect 90 © @100MHz Common Choke in series and ESD suppressors to GND to USB connector	Additional receive signal differential pairs for the SuperSpeed USB data path.
USB_SSTX3+ USB_SSTX3-	D13 D12	O PCIE	AC coupled on Module	AC Coupling capacitor AC Coupling capacitor	Connect 90 \( \to \) @100MHz Common Choke in series and ESD suppressors to GND to USB connector	Additional transmit signal differential pairs for the SuperSpeed USB data path.
USB_SSRX3+	C13	I PCIE	AC coupled off Module	AC Coupling capacitor	Connect 90       @ 100MHz Common Choke in series and ESD suppressors to GND to USB	Additional receive signal differential pairs for the SuperSpeed USB data path.
USB_SSRX3-	C12	I I CIL	ne coupled on module		connector	nadiational receive signal differential pairs for the superspecta obt data pairs.

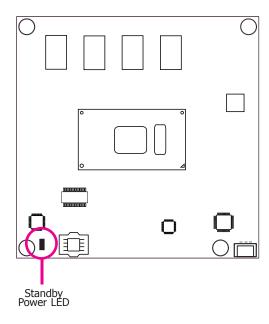
Chapter 3 Hardware Installation www.dfi.com

LVDS Signals Descript		Module Die Tee	Dur Dail / Televene	KIICCO	C	Description			
gnal	Pin#	Module Pin Type	Pwr Rail / Tolerance	KU968	Connect to LVDS connector	Description  LVDS Channel A differential pairs			
/DS_A0+	A71	O LVDS	LVDS		Connect to LVDS connector	Ther LVDS flat panel differential pairs (LVDS_A[0:3]+/-, LVDS_B[0:3]+/ LVDS_A_CK+/-,			
DS_A0-	A72					LVDS B CK+/-) shall have 100Ω terminations across the pairs at the destination. These			
DS_A1+	A73	0.11/00	LV IDG		Connect to LVDS connector	terminations may be on the Carrier Board if the Carrier Board implements a LVDS deserializer			
DS A1-	A74	O LVDS	LVDS		on-board				
DS_A2+	A75				Connect to LVDS connector	on-poard			
		O LVDS	LVDS		Connect to E100 connector				
DS_A2-	A76								
DS_A3+	A78	O LVDS	LVDS		Connect to LVDS connector				
DS_A3-	A79	O LVD3	LVD3						
DS A CK+	A81				Connect to LVDS connector				
DS_A_CK-	A82	O LVDS	LVDS			LVDS Channel A differential clock			
DS_B0+	B71	O LVDS	LVDS		Connect to LVDS connector				
DS_B0-	B72	O LVDS	LVDS			Week of the first of the second of the secon			
DS_B1+	B73	O LV/DC	LVDS		Connect to LVDS connector	LVDS Channel B differential pairs			
DS_B1-	B74	O LVDS	LVDS			Ther LVDS flat panel differential pairs (LVDS_A[0:3]+/-, LVDS_B[0:3]+/-, LVDS_A_CK+/-,			
DS_B2+	B75	O LVDS	LVDS		Connect to LVDS connector	LVDS_B_CK+/-) shall have 100Ω terminations across the pairs at the destination. These terminations may be on the Carrier Board if the Carrier Board implements a LVDS deserializer			
DS_B2-	B76	U LVDS	LVDS			on-board			
DS_B3+	B77	O LVDS	LVDS		Connect to LVDS connector	UI-bualu			
DS_B3-	B78	O LVDS	LVUS						
DS_B_CK+	B81	O LVDS	LVDS		Connect to LVDS connector	LVDS Channel B differential clock			
DS_B_CK-	B82					EVDS CHANNEL & differential clock			
DS_VDD_EN	A77	O CMOS	3.3V / 3.3V		Connect to enable control of LVDS panel power circuit	LVDS panel power enable			
DS_BKLT_EN	B79	O CMOS	3.3V / 3.3V		Connect to enable control of LVDS panel backlight power circuit.	LVDS panel backlight enable			
DS_BKLT_CTRL	B83	O CMOS	3.3V / 3.3V		Connect to brightness control of LVDS panel backlight power circuit.	LVDS panel backlight brightness control			
DS_I2C_CK	A83	I/O OD CMOS	3.3V / 3.3V	PU 4.7K to 3.3V	Connect to DDC clock of LVDS panel	I2C clock output for LVDS display use			
DS_I2C_DAT	A84	I/O OD CMOS	3.3V / 3.3V	PU 4.7K to 3.3V	Connect to DDC data of LVDS panel	I2C data line for LVDS display use			
					•				
PC Signals Description	ons								
nal	Pin#	Module Pin Type	Pwr Rail / Tolerance	KU968	Carrier Board	Description			
C_AD0	B4	rioddic riii rypc	1 W Tany Tolerance	ROSCO	Currier Board	Securition			
C_AD1	B5		<u> </u>						
C AD2	B6	I/O CMOS	3.3V / 3.3V		Connect to LPC device	LPC multiplexed address, command and data bus			
C_AD3	B7		<u> </u>						
C FRAME#	B3	O CMOS	3.3V / 3.3V			LPC frame indicates the start of an LPC cycle			
C_DRQ0#	B8			PU 10K to 3.3V	NC NC	Ere traine indicates the start of an Ere cycle			
C_DRQ1#	B9	I CMOS	3.3V / 3.3V	PU 10K to 3.3V	NC NC	LPC serial DMA request			
PC_DRQ1# PC_SERIRQ	A50	I/O CMOS	3.3V / 3.3V	PU 10K to 3.3V		LPC serial interrupt			
PC_CLK	B10	O CMOS	3.3V / 3.3V	PU 10K to 3.3V	Connect to LPC device	LPC clock output - 24MHz nominal			
PC_CER	DIO	U CINOS	3.30 / 3.30			EPC Clock output - 24Min2 Homiliai			
DI Cianala Docerintia									
PI Signals Descriptio						- · · ·			
gnal	Pin#	Module Pin Type	Pwr Rail / Tolerance	KU968	Carrier Board	Description			
PI_CS#	B97	O CMOS	3.3V Suspend/3.3V		Connect to Carrier Board SPI Device CS# pin	Chip select for Carrier Board SPI - may be sourced from chipset SPI0 or SPI1			
PI_MISO	A92	I CMOS	3.3V Suspend/3.3V		Connect a series resistor 33Ω to Carrier Board SPI Device SO pin	Data in to Module from Carrier SPI			
PI_MOSI	A95	O CMOS	3.3V Suspend/3.3V		Connect a series resistor 33 Ω to Carrier Board SPI Device SI pin	Data out from Module to Carrier SPI			
I_CLK	A94	O CMOS	3.3V Suspend/3.3V		Connect a series resistor $33\Omega$ to Carrier Board SPI Device SCK pin	Clock from Module to Carrier SPI			
						Power supply for Carrier Board SPI - sourced from Module - nominally			
DI DOWED	401		2 21/ 5:			3.3V. The Module shall provide a minimum of 100mA on SPI_POWER.			
PI_POWER	A91	U	3.3V Suspend/3.3V			Carriers shall use less than 100mA of SPI_POWER. SPI_POWER			
						shall only be used to power SPI devices on the Carrier Board.			
			+			Selection straps to determine the BIOS boot device.			
						The Carrier should only float these or pull them low, please refer to			
						below table for strapping options of BIOS disable signals.			
OS_DISO#	A34					below while for surapping options or bros disable signals.			
						BIOS BIOS Chipset Chipset Carrier SPI Bios Ref			
						BIOS BIOS Chipset Chipset Carrier SPI Bios Ref DIS1# DIS0# SPI CS1# SPI CS0# SPI_CS# Descriptor Entry Line			
						Destination Destination			
			l			1 1 Module Module High Module SPI0/SPI1 0			
		I CMOS	NA			1 0 Module Module High Module Carrier FWH 1			
						1 0 Module Module High Module Carrier FWH 1			
						0 1 Module Carrier SPI0 Carrier SPI0/SPI1 2			
OC DIC1#	B88					V I Module Carrier or 10 Carrier SF10/3F11 2			
OS_DIS1#						0 0 Carrier Module SPI1 Module SPI0/SPI1 3			
03_0131#		1				(Default) (Default) (Default) (Default)			
O3_DI31#									
03_0131#						(Solution) (Solution) (Solution)			
US_DI31#						(Southly (Southly (Southly (Southly )			
JS_0131#						(States) (States) (States) (States)			

/GA Signals Descript		Madula Dia To	D D.:I / T.l	KHOCO	Camira Basad	Di-ki
gnal	Pin#	Module Pin Type	Pwr Rail / Tolerance	KU968	Carrier Board	Description
A_RED	B89	O Analog	Analog	PD 150 to GND	PD 150R,connect to VGA connector with EMI filter & ESD protect component.	Red for monitor. Analog output
A_GRN	B91	O Analog	Analog	PD 150 to GND	PD 150R,connect to VGA connector with EMI filter & ESD protect component.	Green for monitor. Analog output
A_BLU	B92	O Analog	Analog	PD 150 to GND	PD 150R,connect to VGA connector with EMI filter & ESD protect component.	Blue for monitor. Analog output
A_HSYNC	B93	O CMOS	3.3V / 3.3V		Connect to VGA connector with a3.3V Buffer IC to isolate PCH & Display Device	
A_VSYNC	B94	O CMOS	3.3V / 3.3V		Connect to VGA connector with a 33V Buffer IC to isolate PCH & Display Device	Vertical sync output to VGA monitor
GA_I2C_CK	B95	I/O OD CMOS	3.3V / 3.3V	PU 2.2K to 3.3V	Connect to VGA connector with a 3.3V to 5V Level shift circuit.	DDC clock line (I2C port dedicated to identify VGA monitor capabilities)
GA_I2C_DAT	B96	I/O OD CMOS	3.3V / 3.3V	PU 2.2K to 3.3V	Connect to VGA connector with a 3.3V to 5V Level shift circuit.	DDC data line.
erial Interface Sign	als Descriptions					
gnal	Pin#	Module Pin Type	Pwr Rail / Tolerance	KU968	Carrier Board	Description Communication of the communication of t
ER0_TX	A98	O CMOS	3.3V/5V		PD 4.7K to GND	General purpose serial port 0 transmitter (Recommend add Protecting Logic Level Signals on Pins Reclaimed from VCC_12V)
						General purpose serial port 0 receiver
ERO_RX	A99	I CMOS	3.3V/5V	PU 10K to 3.3V		(Recommend add Protecting Logic Level Signals on Pins Reclaimed from VCC_12V)
						General purpose serial port 1 transmitter
ER1_TX	A101	O CMOS	3.3V/5V		PD 4.7K to GND	(Recommend add Protecting Logic Level Signals on Pins Reclaimed from VCC_12V)
-D1 DV	A102	I CMOC	2 21//51/	DI 10K +- 2 2V		General purpose serial port 1 receiver
ER1_RX	A102	I CMOS	3.3V/5V	PU 10K to 3.3V		(Recommend add Protecting Logic Level Signals on Pins Reclaimed from VCC_12V)
liscellaneous Signal	l Descriptions					
gnal	Pin#	Module Pin Type	Pwr Rail / Tolerance	KU968	Carrier Board	Description
2C_CK	B33	I/O OD CMOS	3.3V Suspend/3.3V	PU 2.2K to 3V3_DU_EC		General purpose I2C port clock output
C DAT	B34	I/O OD CMOS	3.3V Suspend/3.3V	PU 2.2K to 3V3 DU EC		General purpose I2C port data I/O line
			,,			Output for audio enunciator - the "speaker" in PC-AT systems.
PKR	B32	O CMOS	3.3V / 3.3V			This port provides the PC beep signal and is mostly intended for
IVIV	DJZ	0 (1103	J.JV / J.JV			debugging purposes.
/DT	B27	O CMOS	3.3V / 3.3V			Output indicating that a watchdog time-out event has occurred.
						Fan speed control. Uses the Pulse Width Modulation (PWM) technique to control the fan's RPM.
AN_PWMOUT	B101	O OD CMOS	3.3V / 3.3V			(Recommend add Protecting Logic Level Signals on Pins Reclaimed from VCC_12V)
						Fan tachometer input for a fan with a two pulse output.
AN_TACHIN	B102	I OD CMOS	3.3V / 3.3V	PU 47K to 3V3		(Recommend add Protecting Logic Level Signals on Pins Reclaimed from VCC 12V)
						Trusted Platform Module (TPM) Physical Presence pin. Active high.
PM_PP	A96	I CMOS	3.3V / 3.3V	NA		TPM chip has an internal pull down. This signal is used to indicate
						Physical Presence to the TPM.
ower and System M	lanagement Signal					1 .
	lanagement Signal	S Descriptions Module Pin Type	Pwr Rail / Tolerance	KU968	Carrier Board	Description
			Pwr Rail / Tolerance	KU968	Carrier Board	
ignal	Pin#	Module Pin Type				A falling edge creates a power button event. Power button events can
ignal			Pwr Rail / Tolerance 3.3V Suspend/3.3V	KU968 PU 10K to 3V3_DU_EC	Carrier Board PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of S5 soft off and other suspend states,
ignal	Pin#	Module Pin Type				A falling edge creates a power button event. Power button events can
ignal	Pin#	Module Pin Type				A falling edge creates a power button event. Power button events can be used to bring a system out of S5 soft off and other suspend states, as well as powering the system down.
gnal WRBTN#	Pin# B12	Module Pin Type  I CMOS	3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of S5 soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot.
gnal WRBTN#	Pin#	Module Pin Type				A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is
ignal WRBTN#	Pin# B12	Module Pin Type  I CMOS	3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of S5 soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot.  May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power
ignal WRBTN#	Pin# B12	Module Pin Type  I CMOS	3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of S5 soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot.  May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.
ignal WRBTN#	Pin# B12	Module Pin Type  I CMOS	3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by
WRBTN# YS_RESET#	Pin# 812 B49	I CMOS	3.3V Suspend/3.3V 3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC PU 10K to 3V3_DU	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low
wrbtn# YS_RESET#	Pin# B12	Module Pin Type  I CMOS	3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum
ys_reset#	Pin# 812 B49	I CMOS	3.3V Suspend/3.3V 3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC PU 10K to 3V3_DU	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module
wrbtn# YS_RESET#	Pin# 812 B49	I CMOS	3.3V Suspend/3.3V 3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC PU 10K to 3V3_DU	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum
Power and System Mignal  WRBTN#  YS_RESET#  CB_RESET#	Pin# 812 B49	I CMOS	3.3V Suspend/3.3V 3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC PU 10K to 3V3_DU	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module software.
WRBTN# YS_RESET#	Pin# 812 B49	I CMOS	3.3V Suspend/3.3V 3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC PU 10K to 3V3_DU	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module software.  Power OK from main power supply. A high value indicates that the
ys_reset# B_reset#	Pin# 812 B49	I CMOS	3.3V Suspend/3.3V 3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC PU 10K to 3V3_DU	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module software.  Power OK from main power supply. A high value indicates that the power is good. This signal can be used to hold off Module startup to
gnal WRBTN#  YS_RESET#  B_RESET#	Pin# 812 849 850	I CMOS  I CMOS  O CMOS	3.3V Suspend/3.3V 3.3V Suspend/3.3V 3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC  PU 10K to 3V3_DU  PD 100K to GND	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module software.  Power OK from main power supply. A high value indicates that the power is good. This signal can be used to hold off Module startup to allow Carrier based PFOAS or other configurable devices time to be
vrBTN#  /S_RESET#  B_RESET#	Pin# 812 849 850	I CMOS  I CMOS  O CMOS	3.3V Suspend/3.3V 3.3V Suspend/3.3V 3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC  PU 10K to 3V3_DU  PD 100K to GND	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module software.  Power OK from main power supply. A high value indicates that the power is good. This signal can be used to hold off Module startup to
gnal WRBTN# /S_RESET# B_RESET#	Pin# 812 849 850 824	I CMOS  I CMOS  O CMOS	3.3V Suspend/3.3V 3.3V Suspend/3.3V 3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC  PU 10K to 3V3_DU  PD 100K to GND	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module software.  Power OK from main power supply. A high value indicates that the power is good. This signal can be used to hold off Module startup to allow Carrier based FPGAs or other configurable devices time to be programmed.
ggnal WRBTN#  YS_RESET#  B_RESET#	Pin# 812 849 850	I CMOS  I CMOS  O CMOS	3.3V Suspend/3.3V 3.3V Suspend/3.3V 3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC  PU 10K to 3V3_DU  PD 100K to GND	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module software.  Power OK from main power supply. A high value indicates that the power is good. This signal can be used to hold off Module startup to allow Carrier based FPGAs or other configurable devices time to be programmed.  Indicates imminent suspend operation; used to notify LPC devices.
gnal WRBTN# /S_RESET# B_RESET# WR_OK JS_STAT#	Pin# B12 B49 B50 B24 B18	I CMOS  I CMOS  O CMOS  I CMOS	3.3V Suspend/3.3V 3.3V Suspend/3.3V 3.3V Suspend/3.3V 3.3V J 3.3V 3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC  PU 10K to 3V3_DU  PD 100K to GND  PU 10K to 3V3	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module software.  Power OK from main power supply. A high value indicates that the power is good. This signal can be used to hold off Module startup to allow Carrier based FPGAs or other configurable devices time to be programmed.  Indicates imminent suspend operation; used to notify LPC devices.  Indicates system is in Suspend to RAM state. Active low output. An
yrbtn#  S_reset#  L_reset#  VR_OK	Pin# 812 849 850 824	I CMOS  I CMOS  O CMOS	3.3V Suspend/3.3V 3.3V Suspend/3.3V 3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC  PU 10K to 3V3_DU  PD 100K to GND	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module software.  Power OK from main power supply. A high value indicates that the power is good. This signal can be used to hold off Module startup to allow Carrier based PPGAs or other configurable devices time to be programmed.  Indicates imminent suspend operation; used to notify LPC devices.  Indicates system is in Suspend to RAM state. Active low output. An inverted copy of SUS_S3# on the Carrier Board may be used to
gnal VRBTN#  'S_RESET#  B_RESET#  VR_OK  IS_STAT#  IS_S3#	Pin#  B12  B49  B50  B24  B18  A15	I CMOS  I CMOS  I CMOS  O CMOS  O CMOS  O CMOS  O CMOS	3.3V Suspend/3.3V 3.3V Suspend/3.3V 3.3V Suspend/3.3V 3.3V Suspend/3.3V 3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC  PU 10K to 3V3_DU  PD 100K to GND  PU 10K to 3V3  PD 100K to GND	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module software.  Power OK from main power supply. A high value indicates that the power is good. This signal can be used to hold off Module startup to allow Carrier based PPGAs or other configurable devices time to be programmed.  Indicates imminent suspend operation; used to notify LPC devices.  Indicates system is in Suspend to RAM state. Active low output. An inverted copy of SUS_S3# on the Carrier Board may be used to enable the non-standby power on a typical ATX supply.
gnal VRBTN#  /S_RESET#  B_RESET#  VR_OK  JS_STAT#  JS_S3#	Pin# B12 B49 B50 B24 B18	I CMOS  I CMOS  O CMOS  I CMOS	3.3V Suspend/3.3V 3.3V Suspend/3.3V 3.3V Suspend/3.3V 3.3V J 3.3V 3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC  PU 10K to 3V3_DU  PD 100K to GND  PU 10K to 3V3	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module software.  Power OK from main power supply. A high value indicates that the power is good. This signal can be used to hold off Module startup to allow Carrier based PPGAs or other configurable devices time to be programmed.  Indicates imminent suspend operation; used to notify LPC devices.  Indicates system is in Suspend to RAM state. Active low output. An inverted copy of SUS_S3# on the Carrier Board may be used to
gnal  VRBTN#  /S_RESET#  B_RESET#  VR_OK  US_STAT#  US_S3#  US_S4#	Pin#  B12  B49  B50  B24  B18  A15	I CMOS  I CMOS  I CMOS  O CMOS  O CMOS  O CMOS  O CMOS	3.3V Suspend/3.3V 3.3V Suspend/3.3V 3.3V Suspend/3.3V 3.3V Suspend/3.3V 3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC  PU 10K to 3V3_DU  PD 100K to GND  PU 10K to 3V3  PD 100K to GND	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module software.  Power OK from main power supply. A high value indicates that the power is good. This signal can be used to hold off Module startup to allow Carrier based PFQAs or other configurable devices time to be programmed.  Indicates imminent suspend operation; used to notify LPC devices.  Indicates system is in Suspend to RAM state. Active low output. An inverted copy of SUS_S3# on the Carrier Board may be used to enable the non-standby power on a typical ATX supply.
ignal  WRBTN#  YS_RESET#  B_RESET#  WR_OK  US_STAT#  US_S3#  US_S4#  US_S5#	B12 B49 B50 B24 B18 A15 A18 A24	I CMOS  I CMOS  O CMOS	3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC  PU 10K to 3V3_DU  PD 100K to GND  PU 10K to GND  PD 100K to GND  PD 100K to GND  PD 100K to GND	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module software.  Power OK from main power supply. A high value indicates that the power is good. This signal can be used to hold off Module startup to allow Carrier based FPGAs or other configurable devices time to be programmed.  Indicates system is in Suspend to RAM state. Active low output. An inverted copy of SUS_S3# on the Carrier Board may be used to enable the non-standby power on a typical ATX supply.  Indicates system is in Suspend to Disk state. Active low output.
wrbtn# YS_RESET#	B12  B49  B50  B24  B18  A15	I CMOS  I CMOS  I CMOS  O CMOS  O CMOS  O CMOS  O CMOS	3.3V Suspend/3.3V 3.3V Suspend/3.3V 3.3V Suspend/3.3V 3.3V Suspend/3.3V 3.3V Suspend/3.3V 3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC  PU 10K to 3V3_DU  PD 100K to GND  PU 10K to 3V3  PD 100K to GND  PD 100K to GND	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module software.  Power OK from main power supply. A high value indicates that the power is good. This signal can be used to hold off Module startup to allow Carrier based FPGAs or other configurable devices time to be programmed.  Indicates system is in Suspend to RAM state. Active low output. An inverted copy of SUS_S3# on the Carrier Board may be used to enable the non-standby power on a typical ATX supply.  Indicates system is in Suspend to Disk state. Active low output.  Indicates system is in Suspend to Disk state. Active low output.
yS_RESET#  WR_OK  US_STAT#  US_S3#  US_S5#  US_S5#  UAKEO#	B12  B49  B50  B24  B18  A15  A18  A24  B66	I CMOS  I CMOS  I CMOS  O CMOS  O CMOS  O CMOS  O CMOS  I CMOS  I CMOS  I CMOS  I CMOS	3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC  PU 10K to 3V3_DU  PD 100K to GND  PU 10K to GND  PD 100K to GND  PD 100K to GND  PD 100K to GND  PD 100K to GND  PU 1K to 3V3_DU	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module software.  Power OK from main power supply. A high value indicates that the power is good. This signal can be used to hold off Module startup to allow Carrier based PPGAs or other configurable devices time to be programmed.  Indicates imminent suspend operation; used to notify LPC devices. Indicates system is in Suspend to RAM state. Active low output. An inverted copy of SUS_S3# on the Carrier Board may be used to enable the non-standby power on a typical ATX supply.  Indicates system is in Suspend to Disk state. Active low output. Indicates system is in Suspend to Disk state. Active low output. Indicates system is in Suspend to Disk state. Active low output. Indicates system is in Suspend to Disk state. Active low output. Indicates system is in Soft Off state. PCI Express wake up signal.
yS_RESET#  WR_OK  US_STAT#  US_S3#  US_S5#  US_S5#  UAKEO#	B12 B49 B50 B24 B18 A15 A18 A24	I CMOS  I CMOS  O CMOS	3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC  PU 10K to 3V3_DU  PD 100K to GND  PU 10K to GND  PD 100K to GND  PD 100K to GND  PD 100K to GND	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module software.  Power OK from main power supply. A high value indicates that the power is good. This signal can be used to hold off Module startup to allow Carrier based FPGAs or other configurable devices time to be programmed.  Indicates system is in Suspend to RAM state. Active low output. An inverted copy of SUS_S3# on the Carrier Board may be used to enable the non-standby power on a typical ATX supply.  Indicates system is in Suspend to Disk state. Active low output.  Indicates system is in Suspend to Disk state. Active low output.
yS_RESET#  WR_OK  US_STAT#  US_S3#  US_S5#  US_S5#  UAKEO#	B12  B49  B50  B24  B18  A15  A18  A24  B66	I CMOS  I CMOS  I CMOS  O CMOS  O CMOS  O CMOS  O CMOS  I CMOS  I CMOS  I CMOS  I CMOS	3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC  PU 10K to 3V3_DU  PD 100K to GND  PU 10K to GND  PD 100K to GND  PD 100K to GND  PD 100K to GND  PD 100K to GND  PU 1K to 3V3_DU	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module software.  Power OK from main power supply. A high value indicates that the power is good. This signal can be used to hold off Module startup to allow Carrier based PPGAs or other configurable devices time to be programmed.  Indicates imminent suspend operation; used to notify LPC devices. Indicates system is in Suspend to RAM state. Active low output. An inverted copy of SUS_S3# on the Carrier Board may be used to enable the non-standby power on a typical ATX supply.  Indicates system is in Suspend to Disk state. Active low output. Indicates system is in Suspend to Disk state. Active low output.  General purpose wake up signal.  General purpose wake up signal. May be used to implement wake-up on PS2 keyboard or mouse activity.
gnal WRBTN#  YS_RESET#  B_RESET#  WR_OK  JS_STAT#  JS_S3#  JS_S4#  JS_S5#  JAKE0#  JAKE1#	B12 B49 B50 B24 B18 A15 A18 A24 B66 B67	I CMOS  I CMOS  I CMOS  O CMOS  O CMOS  O CMOS  O CMOS  O CMOS  I CMOS  I CMOS  I CMOS	3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC  PU 10K to 3V3_DU  PD 100K to GND  PU 10K to GND  PD 100K to GND  PD 100K to GND  PD 100K to GND  PD 100K to GND  PU 1K to 3V3_DU  PU 1K to 3V3_DU	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module software.  Power OK from main power supply. A high value indicates that the power is good. This signal can be used to hold off Module startup to allow Carrier based FPGAs or other configurable devices time to be programmed.  Indicates imminent suspend operation; used to notify LPC devices.  Indicates system is in Suspend to RAM state. Active low output. An inverted copy of SUS_S3# on the Carrier Board may be used to enable the non-standby power on a typical ATX supply.  Indicates system is in Suspend to Disk state. Active low output.  Indicates system is in Sost Off state.  PCI Express wake up signal.  General purpose wake up signal. May be used to implement wake-up on PSZ keyboard or mouse activity.  Indicates that external battery is low.
gnal VRBTN#  /S_RESET#  3_RESET#  VR_OK  JS_STAT#  JS_S3#  JS_S4#  JS_S5#  AKE0#  AKE1#	B12  B49  B50  B24  B18  A15  A18  A24  B66	I CMOS  I CMOS  I CMOS  O CMOS  O CMOS  O CMOS  O CMOS  I CMOS  I CMOS  I CMOS  I CMOS	3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC  PU 10K to 3V3_DU  PD 100K to GND  PU 10K to GND  PD 100K to GND  PD 100K to GND  PD 100K to GND  PD 100K to GND  PU 1K to 3V3_DU	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module software.  Power OK from main power supply. A high value indicates that the power is good. This signal can be used to hold off Module startup to allow Carrier based PFQAs or other configurable devices time to be programmed.  Indicates imminent suspend operation; used to notify LPC devices. Indicates system is in Suspend to RAM state. Active low output. An inverted copy of SUS_S3# on the Carrier Board may be used to enable the non-standby power on a typical ATX supply.  Indicates system is in Suspend to Disk state. Active low output. Indicates system is in Suspend to Disk state. Active low output.  Indicates system is in Suspend to Disk state. Active low output.  Indicates system is in Suspend to Disk state. Active low output.  Indicates system is in Suspend to Disk state.  PCI Express wake up signal.  General purpose wake up signal. May be used to implement wake-up on PS2 keyboard or mouse activity.  Indicates that external battery is low.  This port provides a battery-low signal to the Module for orderly
ignal  WRBTN#  YS_RESET#  B_RESET#  WR_OK  US_STAT#  US_S3#  US_S4#  US_S5#	B12 B49 B50 B24 B18 A15 A18 A24 B66 B67	I CMOS  I CMOS  I CMOS  O CMOS  O CMOS  O CMOS  O CMOS  O CMOS  I CMOS  I CMOS  I CMOS	3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC  PU 10K to 3V3_DU  PD 100K to GND  PU 10K to GND  PD 100K to GND  PD 100K to GND  PD 100K to GND  PD 100K to GND  PU 1K to 3V3_DU  PU 1K to 3V3_DU	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module software.  Power OK from main power supply. A high value indicates that the power is good. This signal can be used to hold off Module startup to allow Carrier based FPGAs or other configurable devices time to be programmed.  Indicates imminent suspend operation; used to notify LPC devices.  Indicates system is in Suspend to RAM state. Active low output. An inverted copy of SUS_S3# on the Carrier Board may be used to enable the non-standby power on a typical ATX supply.  Indicates system is in Suspend to Disk state. Active low output.  Indicates system is in Sost Off state.  PCI Express wake up signal.  General purpose wake up signal. May be used to implement wake-up on PSZ keyboard or mouse activity.  Indicates that external battery is low.
gnal VRBTN#  /S_RESET#  3_RESET#  VR_OK  JS_STAT#  JS_S3#  JS_S4#  JS_S5#  AKE0#  AKE1#	B12 B49 B50 B24 B18 A15 A18 A24 B66 B67	I CMOS  I CMOS  I CMOS  O CMOS  O CMOS  O CMOS  O CMOS  O CMOS  I CMOS  I CMOS  I CMOS	3.3V Suspend/3.3V	PU 10K to 3V3_DU_EC  PU 10K to 3V3_DU  PD 100K to GND  PU 10K to GND  PD 100K to GND  PD 100K to GND  PD 100K to GND  PD 100K to GND  PU 1K to 3V3_DU  PU 1K to 3V3_DU	PU 4.7K to 3V3_SB	A falling edge creates a power button event. Power button events can be used to bring a system out of SS soft off and other suspend states, as well as powering the system down.  Reset button input. Active low request for Module to reset and reboot. May be falling edge sensitive. For situations when SYS_RESET# is not able to reestablish control of the system, PWR_OK or a power cycle may be used.  Reset output from Module to Carrier Board. Active low. Issued by Module chipset and may result from a low SYS_RESET# input, a low PWR_OK input, a VCC_12V power input that falls below the minimum specification, a watchdog timeout, or may be initiated by the Module software.  Power OK from main power supply. A high value indicates that the power is good. This signal can be used to hold off Module startup to allow Carrier based PFOAs or other configurable devices time to be programmed.  Indicates imminent suspend operation; used to notify LPC devices. Indicates system is in Suspend to RAM state. Active low output. An inverted copy of SUS_S3# on the Carrier Board may be used to enable the non-standby power on a typical ATX supply.  Indicates system is in Suspend to Disk state. Active low output. Indicates system is in Soft Off state.  PCI Express wake up signal.  General purpose wake up signal. May be used to implement wake-up on PS2 keyboard or mouse activity.  Indicates that external battery is low.  This port provides a battery-low signal to the Module for orderly

	Management Signals D	Module Pin Type	Pwr Rail / Tolerance	KU968	Carrier Board	Description																		
ignal	PIN#	moudie Pin Type	PWI Rall / Tolerance	KU908	Carrier Board	Description																		
						Sleep button. Low active signal used by the ACPI operating system to bring the																		
LEEP#	B103	I OD CMOS	3.3V Suspend/12V	PU 10K to 3V3 DU		system to sleep state or to wake it up again.																		
						(Recommend add Protecting Logic Level Signals on Pins Reclaimed from VCC_12V)																		
HRM#	B35	I CMOS	3.3V / 3.3V	PU 4.7K to 3V3																				
						Input from off-Module temp sensor indicating an over-temp situation.																		
THRMTRIP#		O CMOS	3.3V / 3.3V	PU 10K to 3.3V		Active low output indicating that the CPU has entered thermal shutdown.																		
SMB_CK		I/O OD CMOS	3.3V Suspend/3.3V	PU 2.2K to 3V3_DU_EC		System Management Bus bidirectional clock line.																		
SMB_DAT	B14	I/O OD CMOS	3.3V Suspend/3.3V	PU 2.2K to 3V3_DU_EC		System Management Bus bidirectional data line.																		
SMB_ALERT#	B15	I CMOS	3.3V Suspend/3.3V	PU 2.2K to 3V3_DU_EC		System Management Bus Alert – active low input can be used to generate an SMI# (System Management Interrupt) or to wake the system.																		
CDIO Ciamala Dassai																								
GPIO Signals Descri						le																		
ignal		Module Pin Type	Pwr Rail / Tolerance	KU968	Carrier Board	Description																		
SPO0	A93																							
GPO1	B54	O CMOS	3.3V / 3.3V			General purpose output pins.																		
GPO2	B57	100				Upon a hardware reset, these outputs should be low.																		
GPO3	B63																							
GPI0	A54			PU 100K to 3.3V																				
GPI1	A63	T CMOC	2 21/ / 2 21/	PU 100K to 3.3V		General purpose input pins.																		
GPI2	A67	I CMOS	3.3V / 3.3V	PU 100K to 3.3V		Pulled high internally on the Module.																		
GPI3	A85			PU 100K to 3.3V																				
			1			·																		
Power and GND Sign		M 11 8: T	0.0377	141050		lo es																		
Signal	Pin#	Module Pin Type	Pwr Rail / Tolerance	KU968	Carrier Board	Description																		
	A104~A109																							
VCC_12V	B104~B109	Power				Primary power input: +12V nominal. All available VCC_12V pins on the connector(s) shall be used																		
- · -	C104~C109																							
	D104~D109																							
		Power				Standby power input: +5.0V nominal. If VCC5 SBY is used, all																		
ucc Fix cmy	B84~B87		wer			available VCC 5V SBY pins on the connector(s) shall be used. Only																		
/CC_5V_SBY	B84~B87					used for standby and suspend functions. May be left unconnected if																		
VCC_RTC	A47	Power				Real-time clock circuit-power input. Nominally +3.0V.																		
cc_krc	877	TOWE				real time clock circuit power input. Norminally 13.00.																		
	A1, A11, A21, A31,																							
	A41, A51, A57, A60,																							
	A66, A70, A80, A90,																							
	A100, A110, B1,																							
	B11, B21 ,B31, B41,																							
	B11, B21 ,B31, B41, B51, B60, B70, B80,																							
	B90, B100, B110,																							
	C1, C2, C5, C8, C11,																							
	C14, C21, C31, C41,																							
						Ground - DC power and signal and AC signal return path.																		
	C51, C60, C70, C73,		1			All available GND connector pins shall be used and tied to Carrier																		
GND	C76, C80, C84, C87,	Power				Board GND plane.																		
GND	C76, C80, C84, C87, C90, C93, C96,	Power				Board GND plane.																		
GND	C76, C80, C84, C87, C90, C93, C96, C100, C103, C110,	Power				Board GND plane.																		
GND	C76, C80, C84, C87, C90, C93, C96,	Power				board GNU plane.																		
GND	C76, C80, C84, C87, C90, C93, C96, C100, C103, C110, D1, D2, D5, D8,	Power				воага смо ране.																		
GND	C76, C80, C84, C87, C90, C93, C96, C100, C103, C110, D1, D2, D5, D8, D11, D14, D21,	Power				роаго смо рапе.																		
GND	C76, C80, C84, C87, C90, C93, C96, C100, C103, C110, D1, D2, D5, D8, D11, D14, D21, D31, D51, D60,	Power				воага смо ране.																		
GND	(76, C80, C84, C87, C90, C93, C96, C100, C103, C110, D1, D2, D5, D8, D11, D14, D21, D31, D51, D60, D67, D73,	Power				роаго смо ране.																		
3ND	C76, C80, C84, C87, C90, C93, C96, C100, C103, C110, C103, C110, D1, D2, D5, D8, D11, D14, D21, D31, D51, D60, D67, D70, D73, D76, D80, D84,	Power				воага смо ране.																		
GND	C76, C80, C84, C87, C90, C93, C96, C100, C103, C110, D1, D2, D5, D8, D11, D14, D21, D31, D51, D60, D67, D70, D73, D76, D80, D84, D87, D90, D93,	Power				воаго смо ране.																		
SND	C76, C80, C84, C87, C90, C93, C96, C100, C103, C110, C103, C110, D1, D2, D5, D8, D11, D14, D21, D31, D51, D60, D67, D70, D73, D76, D80, D84,	Power				воага смо ране.																		

## **Standby Power LED**



This LED will be lit when the system is in standby mode.

## **Cooling Option**

#### **Heat Sink**

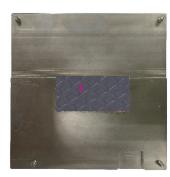


#### Note:

The system board used in the following illustrations may not resemble the actual board. These illustrations are for reference only.



Top View of the Heat Sink



Bottom View of the Heat Sink

 $\bullet$  "1" denotes the location of the thermal pad designed to contact the corresponding components that are on the KU968.



#### [mportant:

Remove the plastic covering from the thermal pads prior to mounting the heat sink onto the KU968.

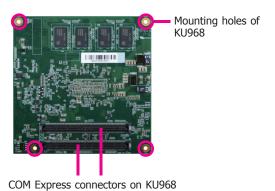
## **Installing KU968 onto a Carrier Board**

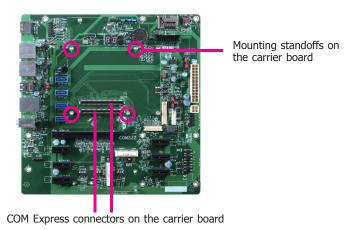
#### Important:



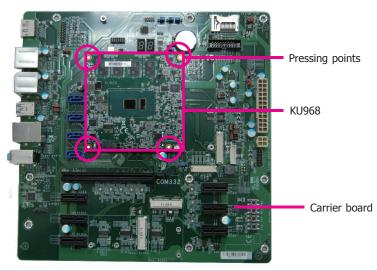
The carrier board (COM332-B) and COM Express module used in this section are for reference purpose only and may not resemble you carrier board and the acutal KU968 module. These illustrations are mainly to guide you on how to install KU968 onto the carrier board of your choice.

 Grasp KU968 by its edges and position it on top of the carrier board with the mounting holes of KU968 aligning with the standoffs on the carrier board. This will also align the COM Express connectors of the two boards to each other.





2. Press KU968 down firmly to seat it in the COM Express connectors of the carrier board.



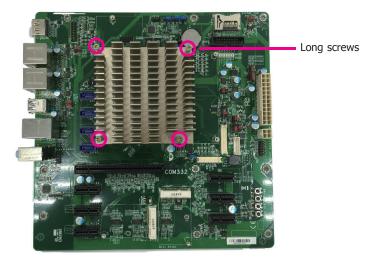
# 事

#### Note:

The illustration above shows the pressing points of the module onto the carrier board. Be careful when pressing the module to avoid damages to the connectors.

22

3. Use the provided mounting screws to secure KU968 with heat sink to the carrie board. The photo below shows the locations of the long mounting screws.



## **Installing the COM Express Debug Card (Optional)**

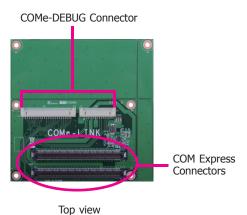
# 事

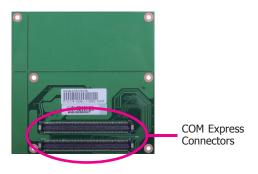
#### Note:

The system board used in the following illustrations may not resemble the actual board. These illustrations are for reference only.

 COMe-LINK1 is the COM Express debug card designed for COM Express Compact modules to debug and display signals and codes of COM Express modules.

#### COMe-LINK1

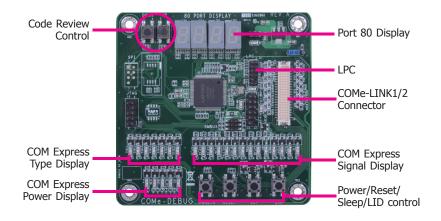


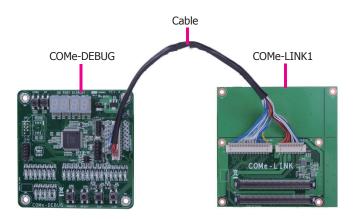


Bottom view

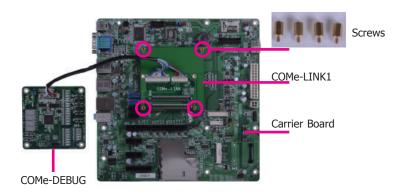
2. Connect the COMe-DEBUG card to COMe-LINK1 via a cable.

#### **COMe-DEBUG**

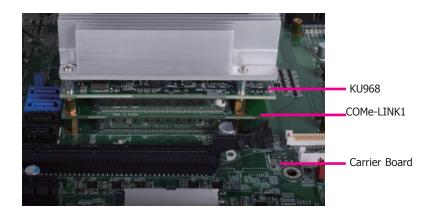




3. Use the provided screws to fix the COMe-LINK1 debug card onto the carrier board.



4. Then use the instructions from the previous section to install SU968 and heat sink on the top of the COMe-LINK1 debug card.



Side View of the Module, Debug Card and Carrier Board

## **Chapter 4 - BIOS Setup**

#### **Overview**

The BIOS is a program that takes care of the basic level of communication between the CPU and peripherals. It contains codes for various advanced features found in this system board. The BIOS allows you to configure the system and save the configuration in a battery-backed CMOS so that the data retains even when the power is off. In general, the information stored in the CMOS RAM of the EEPROM will stay unchanged unless a configuration change has been made such as a hard drive replaced or a device added.

It is possible that the CMOS battery will fail causing CMOS data loss. If this happens, you need to install a new CMOS battery and reconfigure the BIOS settings.



#### Note:

The BIOS is constantly updated to improve the performance of the system board; therefore the BIOS screens in this chapter may not appear the same as the actual one. These screens are for reference purpose only.

## **Default Configuration**

Most of the configuration settings are either predefined according to the Load Optimal Defaults settings which are stored in the BIOS or are automatically detected and configured without requiring any actions. There are a few settings that you may need to change depending on your system configuration.

## **Entering the BIOS Setup Utility**

The BIOS Setup Utility can only be operated from the keyboard and all commands are keyboard commands. The commands are available at the right side of each setup screen.

The BIOS Setup Utility does not require an operating system to run. After you power up the system, the BIOS message appears on the screen and the memory count begins. After the memory test, the message "Press DEL to run setup" will appear on the screen. If the message disappears before you respond, restart the system or press the "Reset" button. You may also restart the system by pressing the <Ctrl> <Alt> and <Del> keys simultaneously.

#### Legends

KEYs	Function
Right and Left Arrows	Moves the highlight left or right to select a menu
Up and Down Arrows	Moves the highlight up or down between submenus or fields
<esc></esc>	Exits to the BIOS setup utility
<f1></f1>	Displays general help
<f5 f6=""></f5>	Changes the highlighted value
<f9></f9>	Changes to the default setup
<f10></f10>	Saves and exits the setup program.
<enter></enter>	Press <enter> to enter the highlighted submenu.</enter>

#### **Scroll Bar**

When a scroll bar appears to the right of the setup screen, it indicates that there are more available fields not shown on the screen. Use the up and down arrow keys to scroll through all the available fields.

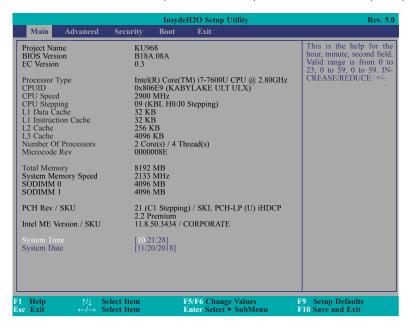
#### Submenu

When " $\blacktriangleright$ " appears on the left of a particular field, it indicates that a submenu which contains additional options are available for that field. To display the submenu, move the highlight to that field and press <Enter>.

## **Insyde BIOS Setup Utility**

#### Main

The Main menu is the first screen that you will see when you enter the BIOS Setup Utility.



#### **System Time**

The time format is <hour>, <minute>, <second>. The time is based on the 24-hour military-time clock. For example, 1 p.m. is 13:00:00. Hour displays hours from 00 to 23. Minute displays minutes from 00 to 59. Second displays seconds from 00 to 59.

#### **System Date**

The date format is <month>, <date>, <year>. Month displays the month, from 01 to 12. Date displays the date, from 01 to 31. Year displays the year, from 2000 to 2099.

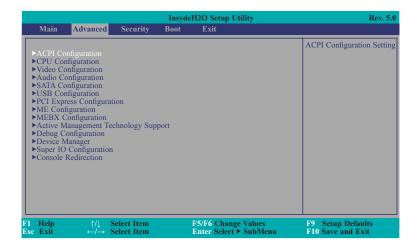
#### **Advanced**

The Advanced menu allows you to configure your system for basic operation. Some entries are defaults required by the system board, while others, if enabled, will improve the performance of your system or let you set some features according to your preference.



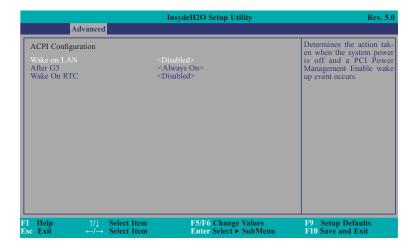
#### Important:

Setting incorrect field values may cause the system to malfunction.



#### **ACPI Configuration**

This section is used to configure the system ACPI parameters.



#### Wake on LAN

This field is used to enable or disable the LAN signal to wake up the system.

#### After G3

This field is to specify what state to go when power is re-applied after a power failure (G3 state).

**Always On** The system working state.

**Always Off** Off, except for trickle current to devices such as the power button.

#### **Wake On RTC**

Automatically power the system on at a particular time every day from the Real-time clock battery.

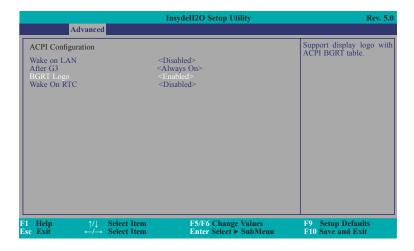
#### Wake up time

When Wake On RTC is set to enabled, specify the wake up time of the day: <hour>(00~23), <minute>(00~59), <second>(00~59).



#### Note:

Under "Dual Boot Type" or "UEFI Boot Type" mode, if "Quiet Boot" is set to enabled, "BGRT Logo" field will appear for configuration. Refer to the "Boot" menu in this chapter for more information.



#### **BGRT Logo**

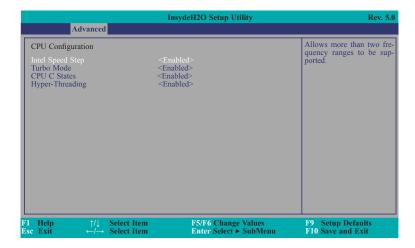
This field is used to enable or disable to support display logo with ACPI BGRT table.

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Chapter 4 BIOS Setup

#### **CPU Configuration**

This section is used to configure the CPU.



#### **Intel Speed Step**

This field is used to enable or disable the Intel Enhanced SpeedStep Technology.

#### **Turbo Mode**

Enable or disable the turbo mode.

#### **CPU C States**

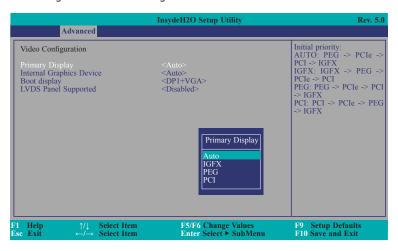
Enable or disable the CPU Power Management.

#### **Hyper-Threading**

Enables this field for Windows XP and Linux which are optimized for Hyper-Threading technology. Select disabled for other OSes not optimized for Hyper-Threading technology.

#### **Video Configuration**

This section configures the video settings.



#### **Primary Display**

Set the initial priority.

#### **Internal Graphics Device**

Keep IGFX enabled or disabled based on the setup options.

#### **Boot display**

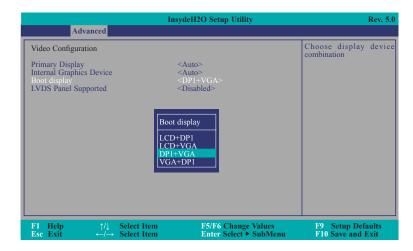
Set the display device combination.



#### Note:

To control "Primary Display" & "Boot display", first go to "Boot" menu and select different "Boot Type".

Boot Type: Legacy Boot Type -> Hide Primary Display & Show Boot display Boot Type: UEFI Boot Type -> Show Primary Display & Hide Boot display Boot Type: Dual Boot Type -> Show Primary Display & Show Boot display



#### **LVDS Panel Supported**

This field is used to enable or disable the PTN3460 function for LVDS Panel. If enabled, "PTN3460 Configuration", "LCD Panel Type" and "Backlight Type" fields will appear for configuration.

#### **PTN3460 Configuration**

Select PTN3460 color depth configuration: 18 Bit, 24 Bit, 36 Bit or 48 Bit.

#### **LCD Panel Type**

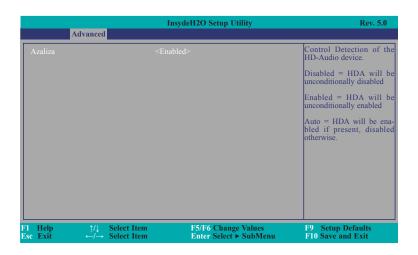
Select LCD Panel Type: 800x480, 800x600, 1024x768, 1366x768, 1280x1024, 1920x1080 or 1920x1200.

#### **Backlight Type**

Select Backlight Type: Normal or Invert.

#### **Audio Configuration**

This section is used to configure the audio settings.



#### **Azaliza**

Control the detection of the Azaliza device.

#### **Disabled**

HDA will be unconditionally disabled.

#### **Enabled**

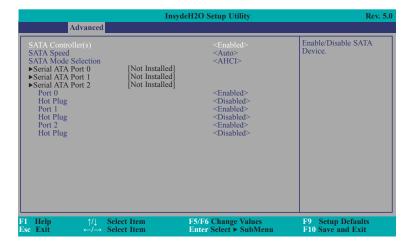
HDA will be unconditionally enabled.

#### Auto

HDA will be enabled if present, disabled otherwise.

#### **SATA Configuration**

This section is designed to select the SATA controller and the type of hard disk drive which are installed in your system unit.



#### SATA Controller(s)

This field is used to enable or disable Serial ATA devices.

#### **SATA Speed**

This field is used to select SATA speed generation limit: Auto, Gen1, Gen2 or Gen3.

#### **SATA Mode Selection**

The mode selection determines how the SATA controller(s) operates.

#### AHCI

This option allows the Serial ATA devices to use AHCI (Advanced Host Controller Interface).

#### **RAID**

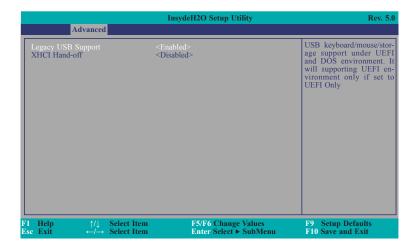
This option allows you to create RAID or Intel Rapid Storage configuration on Serial ATA devices.

#### Port 0/1/2 and Hot Plug

These fields are used to enable or disable the serial ATA ports and their hot plugs.

#### **USB** Configuration

This section is used to configure the parameters of the USB device.



#### **Legacy USB Support**

#### Disabled

Disable USB keyboard/mouse/storage support under UEFI and DOS environment.

#### Enabled

Enable USB keyboard/mouse/storage support under UEFI and DOS environment.

#### **UEFI Only**

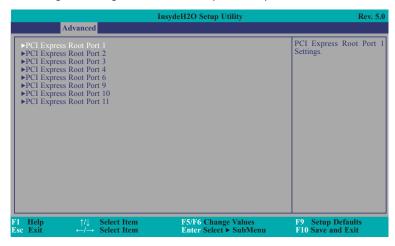
Enable USB keyboard/mouse/storage support under UEFI environment.

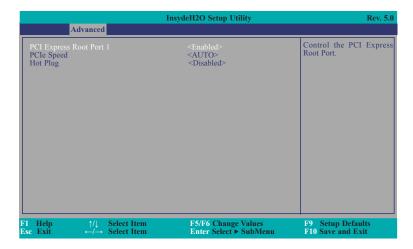
#### **XHCI Hand-off**

Enable or disable to clear USB Legacy SMI bit for XHCI.

#### **PCI Express Configuration**

This section configures settings relevant to PCI Express root ports.





#### PCI Express Root Port 1/2/3/4/6/9/10/11

This field is used to enable or disable the PCI Express Root Port.

#### **PCIe Speed**

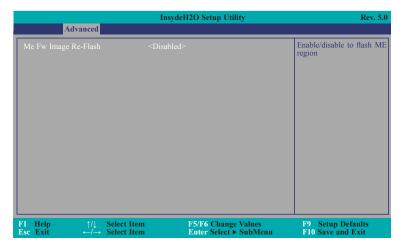
Select the speed of the PCI Express Root Port: Auto, Gen1, Gen2 or Gen3.

#### **Hot Plug**

This field is used to enable or disable the PCI Express Hot Plug.

#### **ME Configuration**

This section configures settings relevant to flash ME region.



#### Me Fw Image Re-Flash

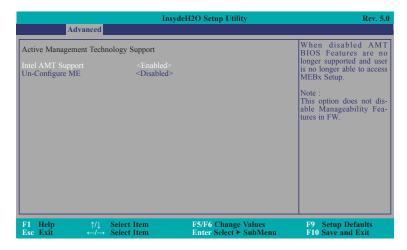
This field is used to enable or disable the flash ME region.

#### **MEBX Configuration**

Configure Intel® Active Management Technology (Intel® AMT) in the Intel® Management Engine BIOS Extension (MEBX) section. Please refer to **Chapter 6** for more information.

#### **Active Management Technology Support**

The section allows users to enable or disable the Intel® Active Management Technology (Intel® AMT). Please refer to **Chapter 6** for more information.



#### **Intel AMT Support**

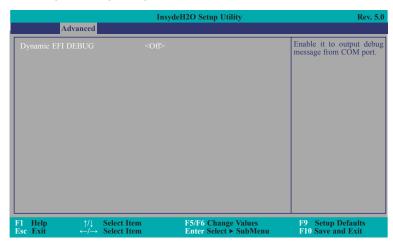
This field is used to enable or disable Intel® Active Management Technology.

#### **Un-Configure ME**

This field is used to enable or disable to un-configure ME with resetting MEBX password to default.

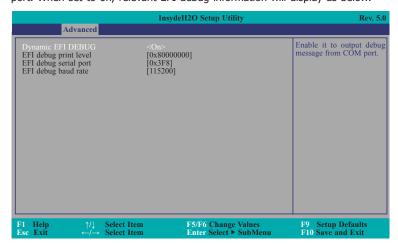
#### **Debug Configuration**

This section configures debug setting.



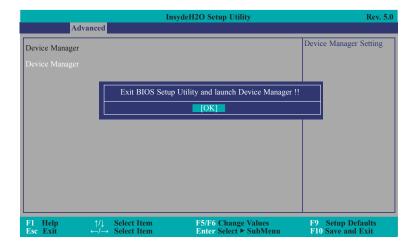
#### **Dynamic EFI DEBUG**

This field is used to turn on or off the function to output debug message from COM port. When set to on, relevant EFI debug information will display as below.



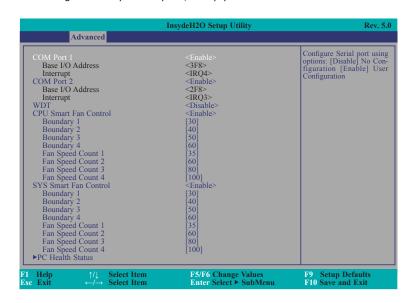
#### **Device Manager**

The section configures UEFI device with option ROM, such as LAN card, etc.



#### **Super IO Configuration**

This section configures the system super I/O chip parameters.



#### COM Port 1/2

Configure the settings to use the serial port.

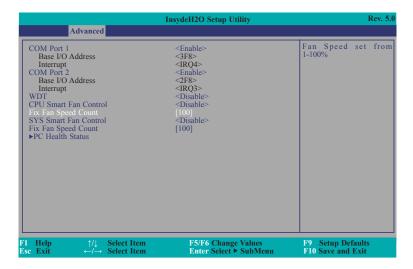
**Disable** No configuration **Enable** User configuration

#### **WDT**

Enable or disable the watchdog function. A counter will appear if you select to enable WDT. Input any value between 1 to 255 seconds.

#### **CPU/SYS Smart Fan Control**

Enable or disable the CPU/System smart fan. When disabled, Fix Fan Speed Count field will appear for configuration.



#### **Fix Fan Speed Count**

Set the fix fan speed. The range is from 1-100% (full speed).

#### **Boundary 1 to Boundary 4**

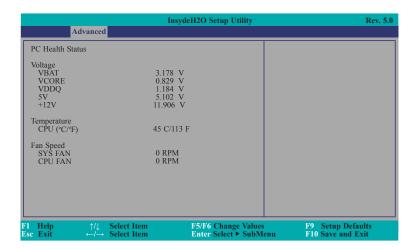
Set the boundary temperatures that determine the operation of the fan with different fan speeds accordingly. For example, when the system or the CPU temperature reaches boundary temperature 1, the system or CPU fan should be turned on and operate at the designated speed. The range is from 0-127°C.

#### Fan Speed Count 1 to Fan Speed Count 4

Set the fan speed. The range is from 1-100% (full speed).

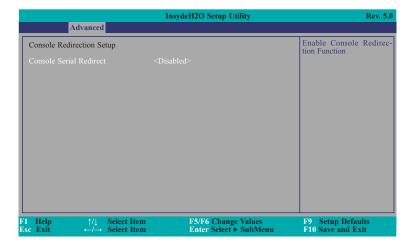
#### **PC Health Status**

This section displays the PC health status.



#### **Console Redirection**

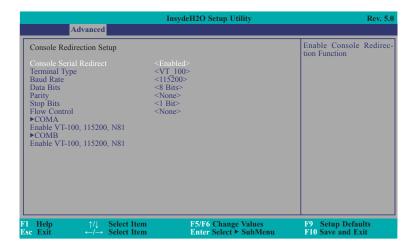
This section configures settings relevant to console redirection.



#### **Console Serial Redirect**

This field is used to enable or disable the console serial redirection function.

When Console Serial Redirect is set to enabled, the screen will appear like below:



## **Terminal Type**

Select terminal type: VT\_100, VT\_100+, VT\_UTF8 or PC\_ANSI.

## **Baud Rate**

Select baud rate: 115200, 57600, 38400, 19200, 9600, 4800, 2400 or 1200.

#### **Data Bits**

Select data bits: 7 Bits or 8 Bits.

#### **Parity**

Select parity bits: None, Even or Odd.

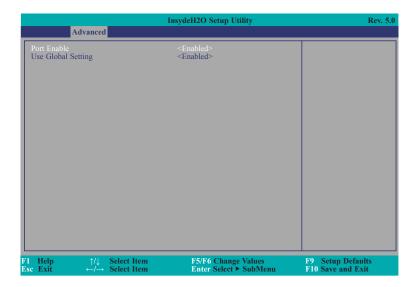
#### **Stop Bits**

Select stop bits: 1 Bit or 2 Bits.

#### **Flow Control**

Select flow control type: None or XON/XOFF.

#### COMA/B



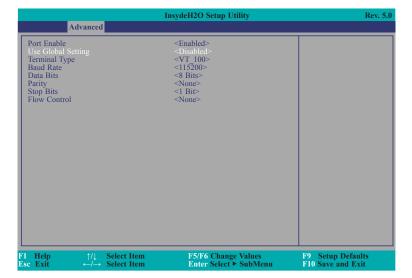
#### **Port Enable**

This field is used to enable or disable the COM port to redirect the console.

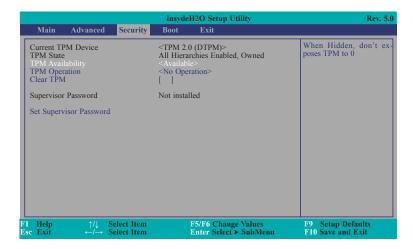
#### **Use Global Setting**

This field is to enable or disable to use global setting. When enabled the global setting, setting of the COM port will be the same as those in Console Redirection section. When disabled the global setting, setting of the COM port can be configured independently in this section.

When Use Global Setting is set to disabled, the screen will appear like below:



# Security



#### **TPM Availability**

Show or hide the TPM availability and its configurations.

#### **TPM Operation**

Select one of the supported operation to change TPM2 state.

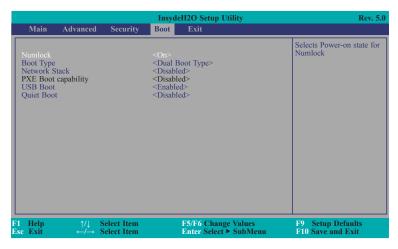
#### **Clear TPM**

Remove all TPM context associated with a specific owner.

#### **Set Supervisor Password**

Set the supervisor's password and the length of the password must be greater than one character.

#### **Boot**



#### Numlock

Select the power-on state for numlock.

### **Boot Type**

Select the boot type. The options are Dual Boot Type, Legacy Boot Type or UEFI Boot Type.

If you select "Dual Boot Type" or "UEFI Boot Type", the "Network Stack", "PXE Boot capability", "USB Boot" and "Quiet Boot" will show up.

If you select "Legacy Boot Type", "PXE Boot to LAN", "USB Boot" and "Quiet Boot" will show up.



#### Note:

If the boot type is set to UEFI, the method for RAID volume creation will be different. Please refer to Chapter 5 – RAID for more information.

#### **Network Stack**

This field is used to enable or disable network stack.

#### **PXE Boot capability**

**Disabled** Suppoort Network Stack

**UEFI** IPv4/IPv6

**Legacy** Legacy PXE OPROM only

#### **PXE Boot to LAN**

Enable or disable PXE boot to LAN.

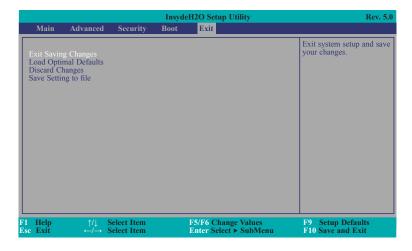
#### **USB Boot**

Enable or disable to change USB boot devices boot order.

#### **Quiet Boot**

Enable or disable booting in text mode.

## **Exit**



#### **Exit Saving Changes**

Select Yes and press <Enter> to exit the system setup and save your changes.

#### **Load Optimal Defaults**

Select YES and press <Enter> to load optimal defaults.

#### **Discard Changes**

Select YES and press <Enter> to exit the system setup without saving your changes.

#### **Save Setting to file**

Select this option to save BIOS configuration settings to a USB flash device.

#### **Restore Setting from file**

This field will appear only when a USB flash device is detected. Select this field to restore setting from the USB flash device.

# **Updating the BIOS**

To update the BIOS, you will need the new BIOS file and a flash utility. Please contact technical support or your sales representative for the files. You may refer to how-to-video, How to update Insyde BIOS in UEFI mode on DFI products?, at https://www.dfi.com/Knowledge/Video/31 for updating the BIOS steps.

#### **Notice: BIOS SPI ROM**

- 1. The Intel® Management Engine has already been integrated into this system board. Due to the safety concerns, the BIOS (SPI ROM) chip cannot be removed from this system board and used on another system board of the same model.
- 2. The BIOS (SPI ROM) on this system board must be the original equipment from the factory and cannot be used to replace one which has been utilized on other system boards.
- 3. If you do not follow the methods above, the Intel® Management Engine will not be updated and will cease to be effective.

# 倉

#### Note:

- a. You can take advantage of flash tools to update the default configuration of the BIOS (SPI ROM) to the latest version anytime.
- b. When the BIOS IC needs to be replaced, you have to populate it properly onto the system board after the EEPROM programmer has been burned and follow the technical person's instructions to confirm that the MAC address should be burned or not.

# **Chapter 5 - Supported Software**

Please download drivers, utilities and software applications required to enhance the performance of the system board at https://www.dfi.com/DownloadCenter .

# **Intel Chipset Software Installation Utility**

The Intel Chipset Software Installation Utility is used for updating Windows® INF files so that the Intel chipset can be recognized and configured properly in the system.

To install the utility, download "KU968 Chipset Driver" zip file at our website.

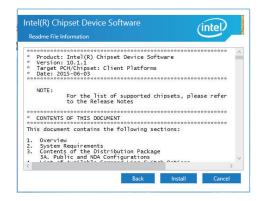
1. Setup is ready to install the utility. Click "Next".



2. Read the license agreement then click "Accept".



 Go through the readme document for more installation tips then click "Install".

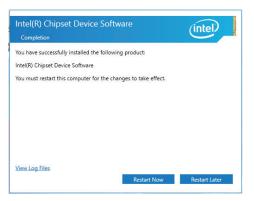


 The step displays the installing status in the progress.



5. After completing installation, click "Restart Now" to exit setup.

Restarting the system will allow the new software installation to take effect.



# **Intel Graphics Drivers**

To install the driver, download "KU968 Graphics Driver" zip file at our website.

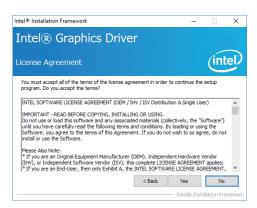
 Setup is now ready to install the graphics driver. Click "Next".



By default, the "Automatically run WinSAT and enable the Windows Aero desktop theme" is enabled. With this enabled, after installing the graphics driver and the system rebooted, the screen will turn blank for 1 to 2 minutes (while WinSAT is running) before the Windows 10 desktop appears. The "blank screen" period is the time Windows is testing the graphics performance.

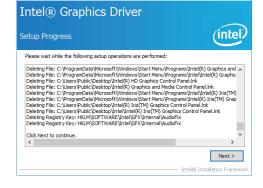
We recommend that you skip this process by disabling this function then click "Next".

2. Read the license agreement then click "Yes".



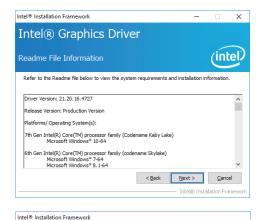
3. Go through the readme document for system requirements and installation tips then click "Next".

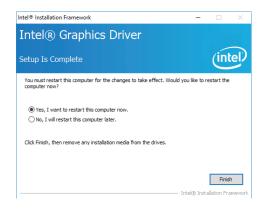
 Setup is now installing the driver. Click "Next" to continue.



5. Click "Yes, I want to restart this computer now" then click "Finish".

Restarting the system will allow the new software installation to take effect.





# **Audio Drivers**

To install the driver, download "KU968 Audio Driver" zip file at our website.

Setup is ready to install the driver. Click "Next".



Click "Yes, I want to restart my computer now" then click "Finish".

Restarting the system will allow the new software installation to take effect.

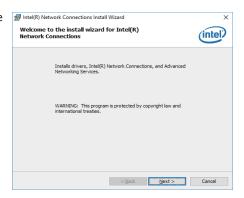


## **Intel LAN Drivers**

To install the driver, download "KU968 LAN Driver" zip file at our website.

 Setup is ready to install the driver. Click "Next".

 # Intel(R) Network Connections Install Wizard
 Welcome to the install wizard for Intel
 Welcome to the install wizard for Intel
 # Intel(R) Network Connections Install Wizard
 Welcome to the install wizard for Intel
 # Intel(R) Network Connections Install Wizard
 # Intel(R) Network Connections

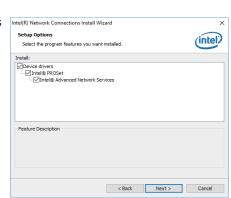


Click "I accept the terms in the license agreement" then click "Next".

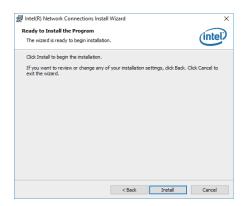


3. Select the program features you want installed then click "Next".

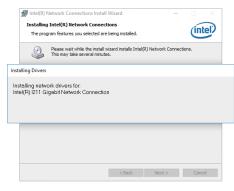
Intel(R) Network Connections Install Wizard Setup Options
Select the program features you want install Connections Install Wizard Setup Options
Select the program features you want install Connections Install Wizard Setup Options



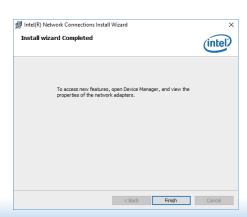
4. Click "Install" to begin the installation.



The step displays the installing status in the progress.



6. After completing installation, click "Finish".



# **Intel Management Engine Drivers**

To install the driver, download "KU968 MEI Driver" zip file at our website.

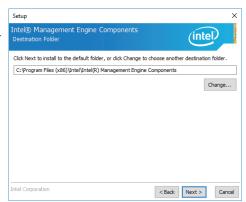
1. Setup is ready to install the driver. Click "Next".



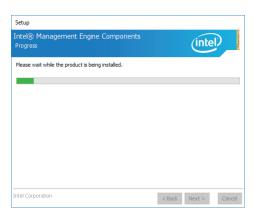
2. Read the license agreement then tick "I accept the terms in the License Agreement". Click "Next".



 Click "Next" to install to the default folder, or click "Change" to choose another destination folder.



4. Please wait while the product is being installed.



5. After completing installation, click "Finish".

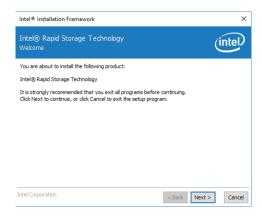


# **Intel Rapid Storage Technology**

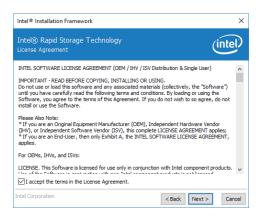
The Intel Rapid Storage Technology is a utility that allows you to monitor the current status of the SATA drives. It enables enhanced performance and power management for the storage subsystem.

To install the driver, download "KU968 Intel Rapid Storage Driver" zip file at our website.

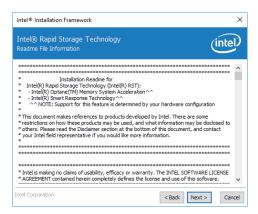
1. Setup is ready to install the utility. Click "Next".



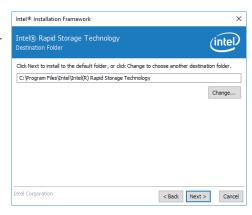
 Read the license agreement and click "I accept the terms in the License Agreement". Then, click "Next".



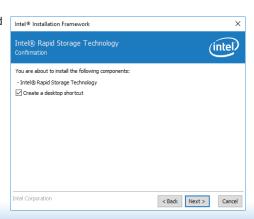
 Go through the readme document to view system requirements and installation information then click "Next".



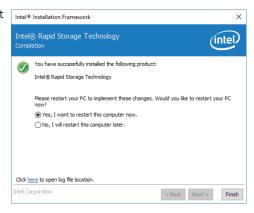
 Click "Next" to install to the default folder or click "Change to choose another destination folder".



5. Confirm the installation and click "Next".



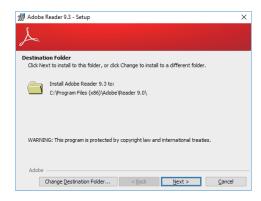
6. Click "Yes, I want to restart this computer now" to complete the installation and then click "Finish".



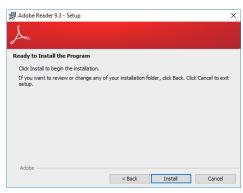
# **Adobe Acrobat Reader 9.3**

To install the reader, download "KU968 Driver Package" iso file at our website. Click "Adobe Acrobat Reader 9.3".

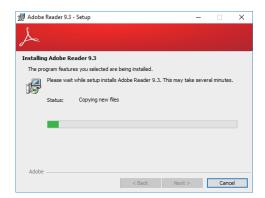
 Click "Next" to install or click "Change Destination Folder" to select another folder.



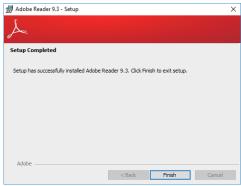
2. Click "Install" to begin installation.



3. Setup is now installing the driver.



4. Click "Finish" to exit installation.



## **SIO Driver**

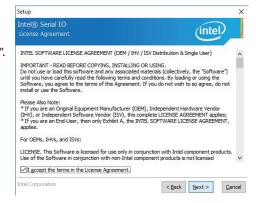
To install the driver, download "KU968 SIO Driver" zip file at our website.

 Setup is ready to install the driver. Click "Next".

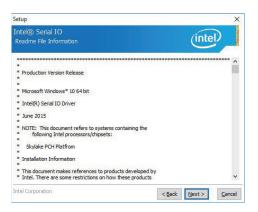


2. Read the license agreement carefully.

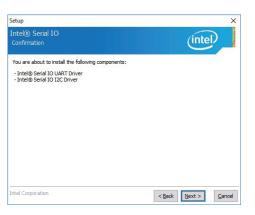
Click "I accept the terms in the License Agreement" then click "Next".



3. Read the file information then click "Next".



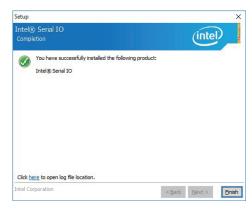
4. Setup is ready to install the driver. Click "Next".



5. Setup is now installing the driver.



6. Click "Finish".



Chapter 5 Supported Software www.dfi.com

# **Chapter 6 - RAID**

The system board allows configuring RAID on Serial ATA drives. It supports RAID 0, RAID 1, and RAID 5.

#### **RAID Levels**

# **RAID 0 (Striped Disk Array without Fault Tolerance)**

RAID 0 uses two new identical hard disk drives to read and write data in parallel, interleaved stacks. Data is divided into stripes and each stripe is written alternately between two disk drives. This improves the I/O performance of the drives at different channel; however it is not fault tolerant. A failed disk will result in data loss in the disk array.

# **RAID 1 (Mirroring Disk Array with Fault Tolerance)**

RAID 1 copies and maintains an identical image of the data from one drive to the other drive. If a drive fails to function, the disk array management software directs all applications to the other drive since it contains a complete copy of the drive's data. This enhances data protection and increases fault tolerance to the entire system. Use two new drives or an existing drive and a new drive but the size of the new drive must be the same or larger than the existing drive.

#### RAID 5

RAID 5 stripes data and parity information across hard drives. It is fault tolerant and provides better hard drive performance and more storage capacity.

RAID Level	Min. Drives	Protection	Description
RAID 0	2	None	Data striping without redundancy
RAID 1	2	Single Drive Failure	Disk mirroring
RAID 5	3	Single Drive Failure	Block-level data striping with distributed parity
RAID 10	4	1 Disk Per Mirrored Stripe (not same mirror)	Combination of RAID 0 (data striping) and RAID 1 (mirroring)

# **Settings**

To enable the RAID function, the following settings are required.

- 1. Connect the Serial ATA drives.
- 2. Enable Serial ATA in the Insyde BIOS.
- 3. Create a RAID volume.
- 4. Install the Intel Rapid Storage Technology Utility.

## **Step 1: Connect the Serial ATA Drives**

Refer to Chapter 2 for details on connecting the Serial ATA drives.



#### Important:

- 1. Make sure you have installed the Serial ATA drives and connected the data cables otherwise you won't be able to enter the RAID BIOS utility.
- Treat the cables with extreme caution especially while creating RAID. A damaged cable will ruin the entire installation process and operating system. The system will not boot and you will lost all data in the hard drives. Please give special attention to this warning because there is no way of recovering back the data.

# **Step 2: Enable RAID in the Insyde BIOS**

- 1. Power-on the system then press <Del> to enter the main menu of the Insyde BIOS.
- 2. Go to "Advanced" menu, and select the "SATA Configuration" menu.
- 3. Change the "SATA Mode Selection" to "RAID" mode.
- 4. Save the changes in the "Save & Exit" menu.
- Reboot the system.

Chapter 6 RAID www.dfi.com

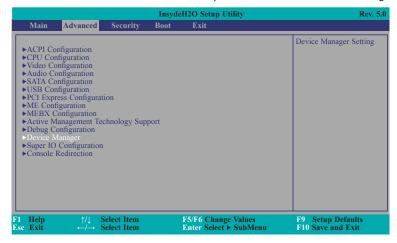
## **Step 3: Create a RAID Volume**

- 1. When the Intel® RST option ROM status screen displays during POST, press <Ctrl> and <I> simultaneously to enter the option ROM user interface.
- 2. Select 1: Create RAID Volume and press <Enter>.
- 3. Create a volume name and press <Enter>.
- 4. Use the up or down arrow keys to select the RAID level and press <Enter>.
- 5. Use the up or down arrow keys to select the strip size and press <Enter>.
- 6. Select the capacity and press <Enter>. You must select less than one hundred percent of the available volume space to leave space for the second volume.
- 7. Press <Enter> to create the volume.
- 8. At the prompt, press <Y> to confirm volume creation.
- 9. Select 4: Exit and press <Enter>.
- 10. Press <Y> to confirm exit.

## **Step 3-1: Create a RAID Volume if the boot type is UEFI**

If the boot type is set to UEFI, RAID volume creation will be different. Please use the following steps to create RAID volumes. To set the boot type, enter the Insyde BIOS and go to "Boot" > "Boot Type".

1. Go to the "Advanced" menu of the Insyde BIOS and select "Device Manager".



- 2. The screen displays all available drives. Select "Create RAID volume" to create a RAID volume".
- 3. Use the up or down arrow keys to select the RAID level and press <Enter>.
- Use the up or down arrow keys to scroll through the list of hard drives and press <Enter> to select the drive.
- 5. Press <Enter>.
- 6. Use the up or down arrow keys to select the strip size and press <Enter>.
- 7. Enter the volume size and press <Enter>.
- 8. At the prompt, press <Y> to confirm volume creation.

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# **Step 4: Install the Intel Rapid Storage Technology Utility**

The Intel Rapid Storage Technology Utility can be installed from within Windows. It allows RAID volume management (create, delete, migrate) from within the operating system. It will also display useful SATA device and RAID volume information. The user interface, tray icon service and monitor service allow you to monitor the current status of the RAID volume and/ or SATA drives. It enables enhanced performance and power management for the storage subsystem.

To install the driver, please refer to Chapter 5 for more information.

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# **Chapter 7 - Intel AMT Settings**

## **Overview**

Intel Active Management Technology (Intel® AMT) combines hardware and software solution to provide maximum system defense and protection to networked systems.

The hardware and software information are stored in non-volatile memory. With its built-in manageability and latest security applications, Intel® AMT provides the following functions.

#### Discover

Allows remote access and management of networked systems even while PCs are powered off; significantly reducing desk-side visits.

## Repair

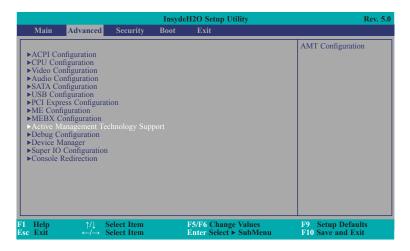
Remotely repair systems after OS failures. Alerting and event logging help detect problems quickly to reduce downtime.

#### Protect

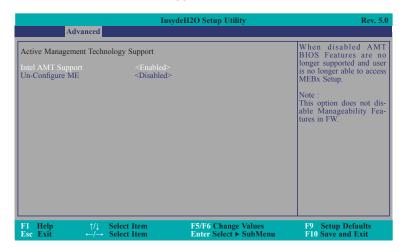
Intel AMT's System Defense capability remotely updates all systems with the latest security software. It protects the network from threats at the source by proactively blocking incoming threats, reactively containing infected clients before they impact the network, and proactively alerting when critical software agents are removed.

# **Enable Intel® AMT in the Insyde BIOS**

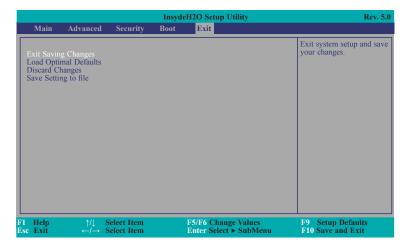
- 1. Power-on the system then press <Del> to enter the main menu of the Insyde BIOS.
- 2. In the **Advanced** menu, select **Active Management Technology Support**.



3. Select **Enabled** in the **Intel AMT Support** field.

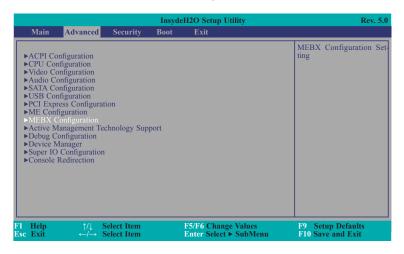


4. In the **Exit** menu, select **Exit Saving Changes** then select **Yes** and press Enter.

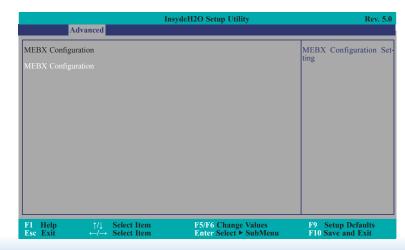


# Enable Intel® AMT in the Intel® Management Engine BIOS Extension (MEBX) Screen

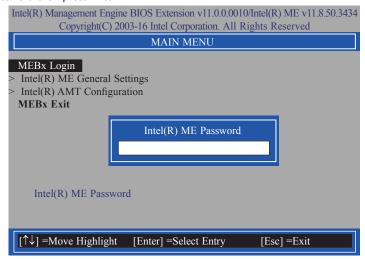
- 1. After the system reboots, press <Del> to enter the main menu of the Insyde BIOS.
- 2. In the **Advanced** menu, select **MEBX Configuration**.



3. Select **MEBX Configuration** and press Enter.



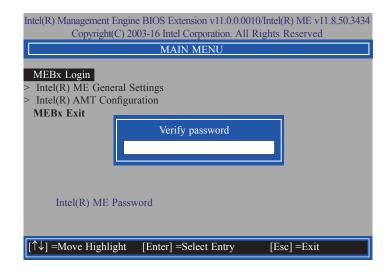
4. Select **MEBx Login** and press Enter. You will be prompted for a password. The default password is "admin". Enter the default password in the space provided under Intel(R) ME Password then press Enter.



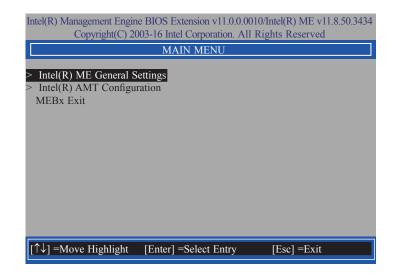
- 5. Enter a new password in the space provided under Intel(R) ME New Password then press Enter. The password must include:
  - 8-32 characters
  - Strong 7-bit ASCII characters excluding:, and " characters
  - At least one digit character (0, 1, ...9)
  - At least one 7-bit ASCII non alpha-numeric character, above 0x20, (e.g. !, \$, ;)
  - Both lower case and upper case characters



6. You will be asked to verify the new password. Enter the same new password in the space provided under Verify Password then press Enter.



7. Select Intel(R) ME General Settings then press Enter.



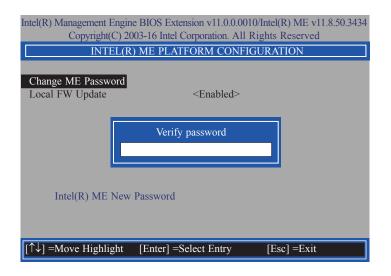
8. If you want to change ME password, select **Change ME Password** then press Enter. Enter the current password in the space provided under Intel(R) ME Password then press Enter.



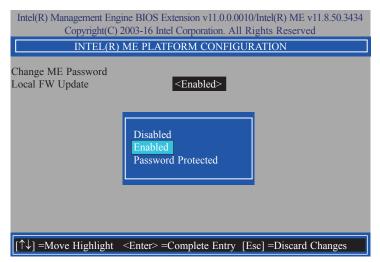
- 9. Enter a new password in the space provided under Intel(R) ME New Password then press Enter. The password must include:
  - 8-32 characters
  - Strong 7-bit ASCII characters excluding:, and " characters
  - At least one digit character (0, 1, ...9)
  - At least one 7-bit ASCII non alpha-numeric character, above 0x20, (e.g. !, \$, ;)
  - Both lower case and upper case characters



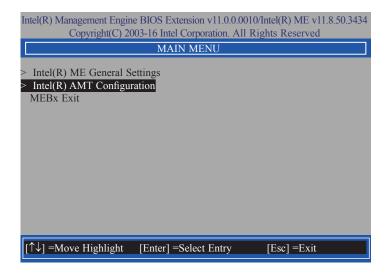
10. You will be asked to verify the new password. Enter the same new password in the space provided under Verify Password then press Enter.



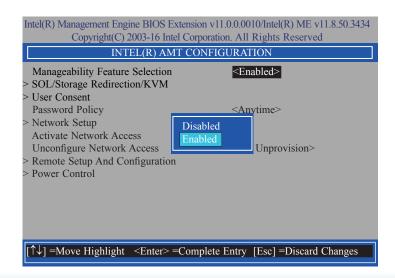
 Select Local FW Update then press Enter. Select Enabled or Disabled or Password Protected then press Enter.



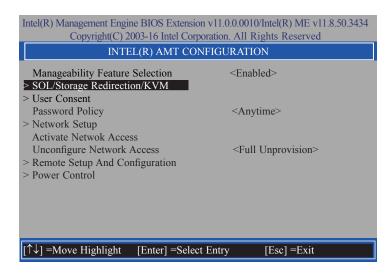
12. Press Esc until you return to the **Main Menu**. Select **Intel(R) AMT Configuration** then press Enter.



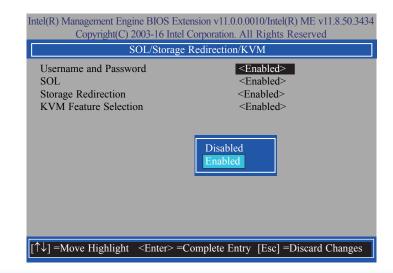
 In the Intel(R) AMT Configuration menu, select Manageability Feature Selection then press Enter. Select Enabled or Disabled then press Enter.



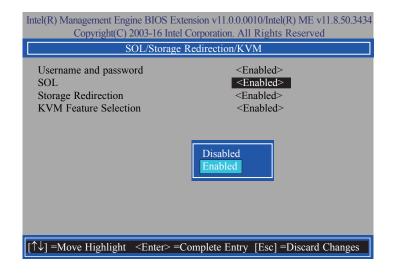
 In the Intel(R) AMT Configuration menu, select SOL/Storage Redirection/KVM then press Enter.



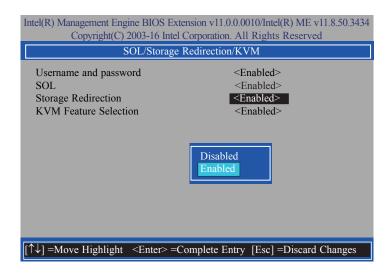
 In the SOL/Storage Redirection/KVM menu, select Username and Password then press Enter. Select Enabled or Disabled then press Enter.



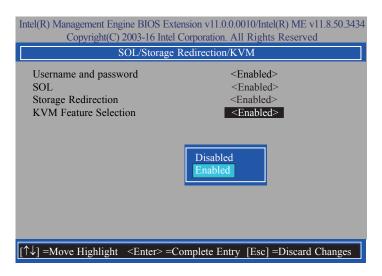
16. Select **SOL** then press Enter. Select **Enabled** or **Disabled** then press Enter.



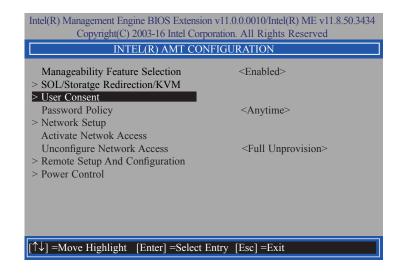
 Select Storage Redirection then press Enter. Select Enabled or Disabled then press Enter.



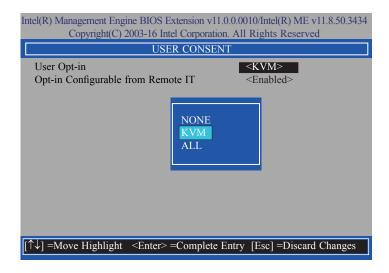
 Select KVM Feature Selection then press Enter. Select Enabled or Disabled then press Enter.



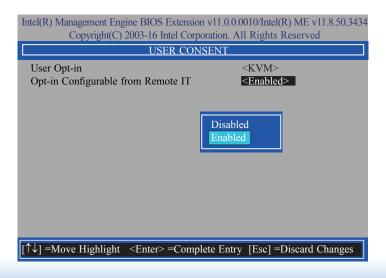
 Press Esc until you return to the Intel(R) AMT Configuration menu. Select User Consent then press Enter.



 In the User Consent menu, select User Opt-in then press Enter. Select NONE or KVM or ALL then press Enter.

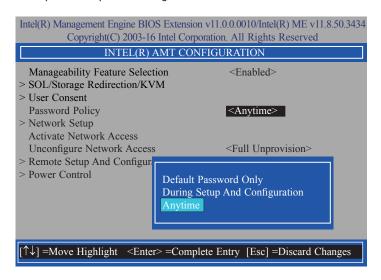


21. Select **Opt-in Configurable from Remote IT** then press Enter. Select **Enabled** or **Disabled** then press Enter.

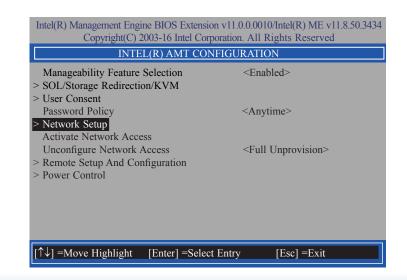


22. Press Esc until you return to the **Intel(R) AMT Configuration** menu. Select **Password Policy** then press Enter.

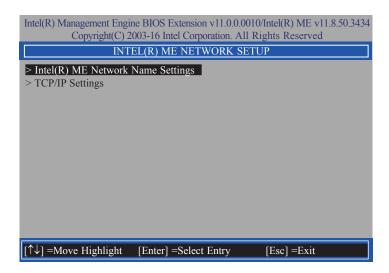
You may choose to use a password only during setup and configuration or to use a password anytime the system is being accessed.



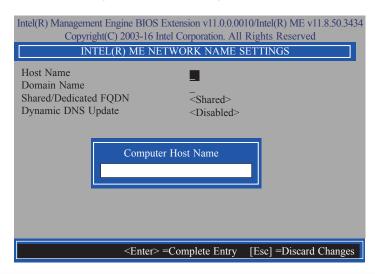
23. In the Intel(R) AMT Configuration menu, select Network Setup then press Enter.



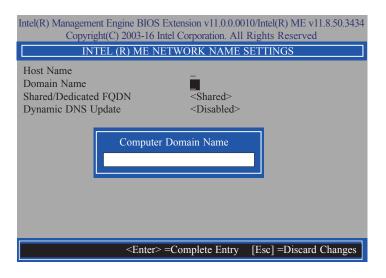
24. In the Intel(R) ME Network Setup menu, select Intel(R) ME Network Name Settings then press Enter.



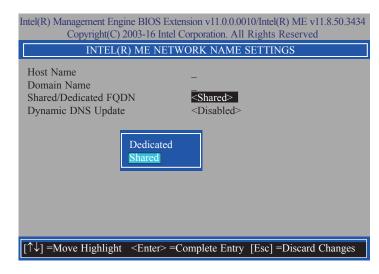
25. In the **Intel(R) ME Network Name Settings** menu, select **Host Name** then press Enter. Enter the computer's host name then press Enter.



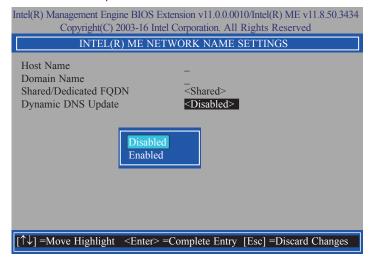
 Select **Domain Name** then press Enter. Enter the computer's domain name then press Enter.



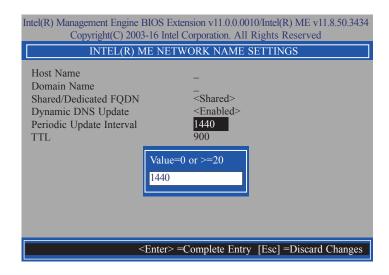
 Select Shared/Dedicated FQDN then press Enter. Select Shared or Dedicated then press Enter.



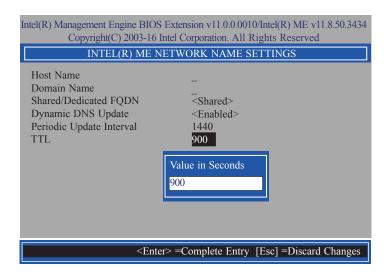
 Select Dynamic DNS Update then press Enter. Select Enabled or Disabled then press Enter. If Dynamic DNS Update is set to Enabled, Periodic Update Interval and TTL fields will show up.



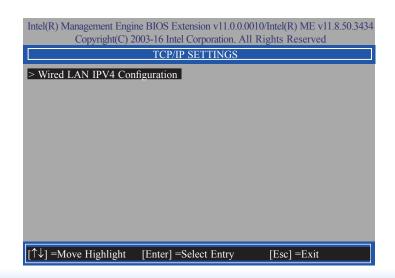
29. Select **Periodic Update Interval** then press Enter. Enter value then press Enter.



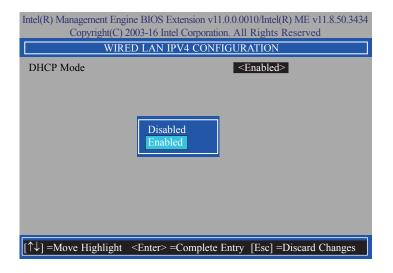
30. Select **TTL** then press Enter. Enter value then press Enter.



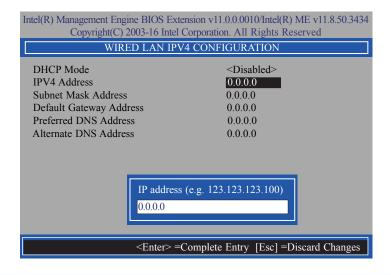
 Press Esc until you return to the Intel(R) ME Network Setup menu. Select TCP/IP Settings then press Enter. In the TCP/IP Settings menu, select Wired LAN IPV4 Configuration then press Enter.



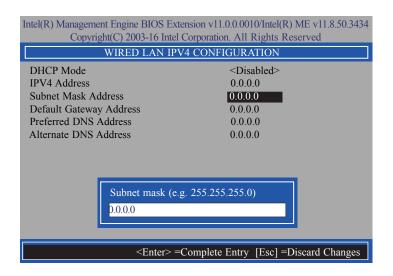
32. In the Wired LAN IPV4 Configuration menu, select DHCP Mode then press Enter. Select Enabled or Disabled then press Enter. If set to Disabled, IPV4 Address, Subnet Mask Address, Default Gateway Address, Preferred DNS Address and Alternate DNS Address will show up.



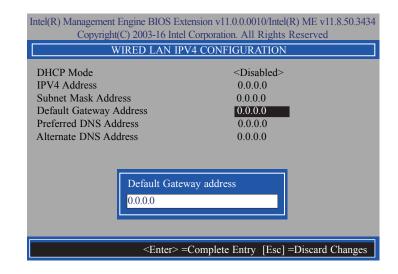
33. Select **IPV4 Address** then press Enter. Enter address then press Enter.



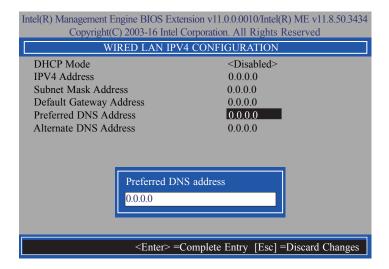
34. Select **Subnet Mask Address** then press Enter. Enter address then press Enter.



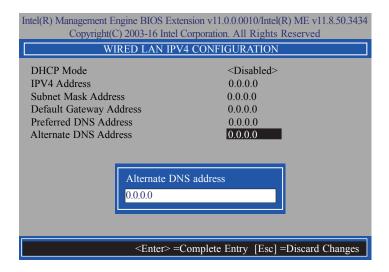
35. Select **Default Gateway Address** then press Enter. Enter address then press Enter.



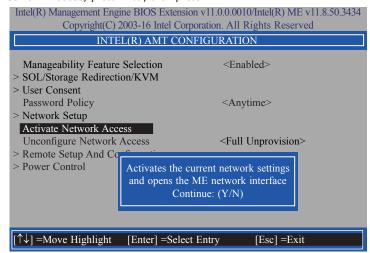
36. Select **Preferred DNS Address** then press Enter. Enter address then press Enter.



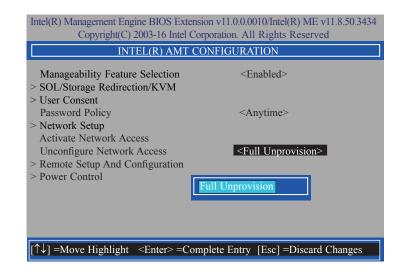
37. Select **Alternate DNS Address** then press Enter. Enter address then press Enter.



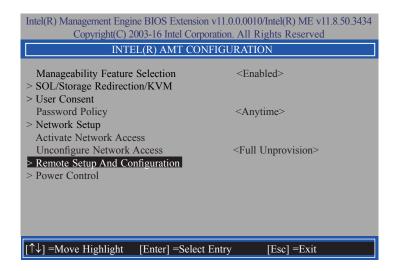
38. Press Esc until you return to the **Intel(R) AMT Configuration** menu. If you want to activate the current network settings and open the ME network inferface, select **Activate Network Access**, press Enter, then press Y.



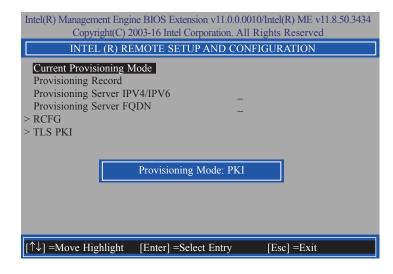
 In the Intel(R) AMT Configuration menu, select Unconfigure Network Access then press Enter.



40. In the Intel(R) AMT Configuration menu, select Remote Setup And Configuration then press Enter.



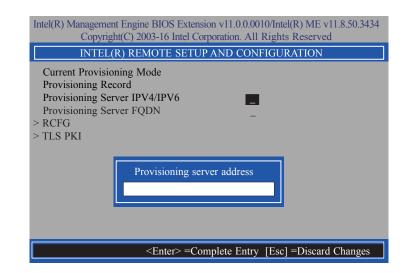
 In the Intel(R) Remote Setup And Configuration menu, select Current Provisioning Mode then press Enter.



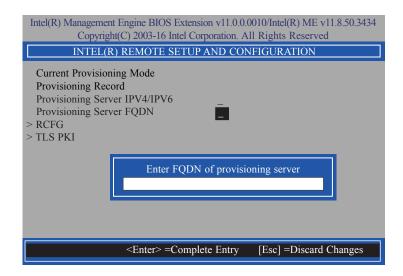
In the Intel(R) Remote Setup And Configuration menu, select Provisioning Record then press Enter.



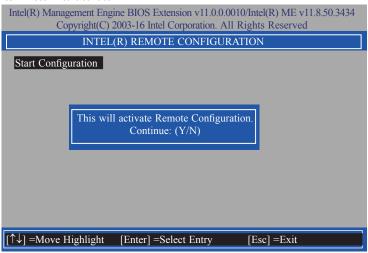
43. In the Intel(R) Remote Setup And Configuration menu, select Provisioning Server IPV4/IPV6 then press Enter. Enter the address then press Enter.



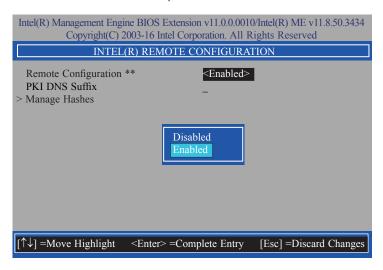
44. In the Intel(R) Remote Setup And Configuration menu, select Provisioning Server FQDN then press Enter. Enter the FQDN then press Enter.



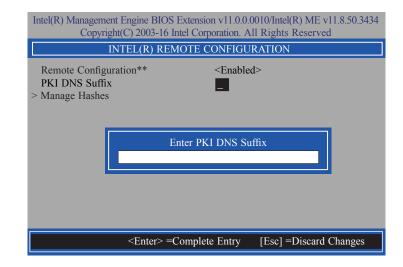
45. If you want to activate remote configuration, in the Intel(R) Remote Setup And Configuration menu, select RCFG then press Enter. Select Start Configuration then press Enter. Press Y to activate.



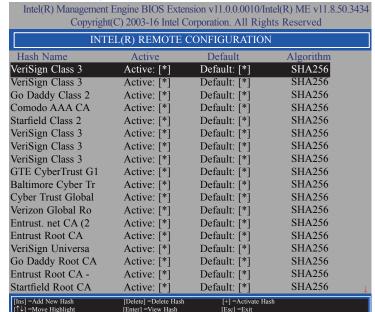
46. Press Esc until you return to the **Intel(R) Remote Setup And Configuration** menu. Select **TLS PKI** then press Enter. Select **Remote Configuration** \*\* then press Enter. Select **Enabled** or **Disabled** then press Enter.



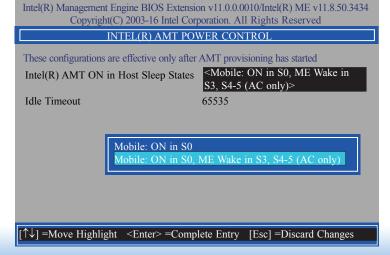
47. Select **PKI DNS Suffix** then press Enter. Enter the PKI DNS Suffix then press Enter.



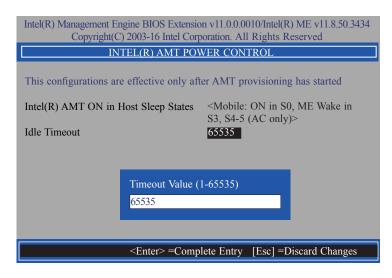
48. In the **Intel(R) Remote Configuration** menu, select **Manage Hashes** then press Enter. Select the hash name then press Insert to enter custom hash certificate name, press Delete to delete hash, press Enter to view hash information, press + to activate or deactivate hash, and press Esc to exit.



49. Press Esc until you return to the Intel(R) AMT Configuration menu, select Power Control then press Enter. In the Intel(R) AMT Power Control menu, select Intel(R) AMT ON in Host Sleep States then press Enter. Select an option then press Enter.



50. In the **Intel(R) AMT Power Control** menu, select **Idle Timeout** then press Enter. Enter the timeout value and press Enter.



51. Press Esc until you return to the **Main Menu**. Select **MEBx Exit** then press Enter. Press Y to exit.

